

Revision History

Version	Date	By	Change Dscription	Approved
V1.0	2021-06-01		1:Revision preliminary version	
V1.1	2021-06-29			
V1.2	2021-07-24			
V1.3	2021-09-13			



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- 31.Power_CPU_RTC
- 32.Power_PMIC
- 33.Power-DC IN

Description

Note

Option

Generate Bill of Materials

Header:

Item\Part\Description\PCB Footprint\Reference\Quantity\Option

Combined property string:

{Item}\{Value}\{Description}\{PCB Footprint}\{Reference}\{Quantity}\{Option}

Notes

NOTE 1:

Component parameter description

1. DNP stands for component not mounted temporarily
2. If Value or option is DNP, which means the area is reserved without being mounted

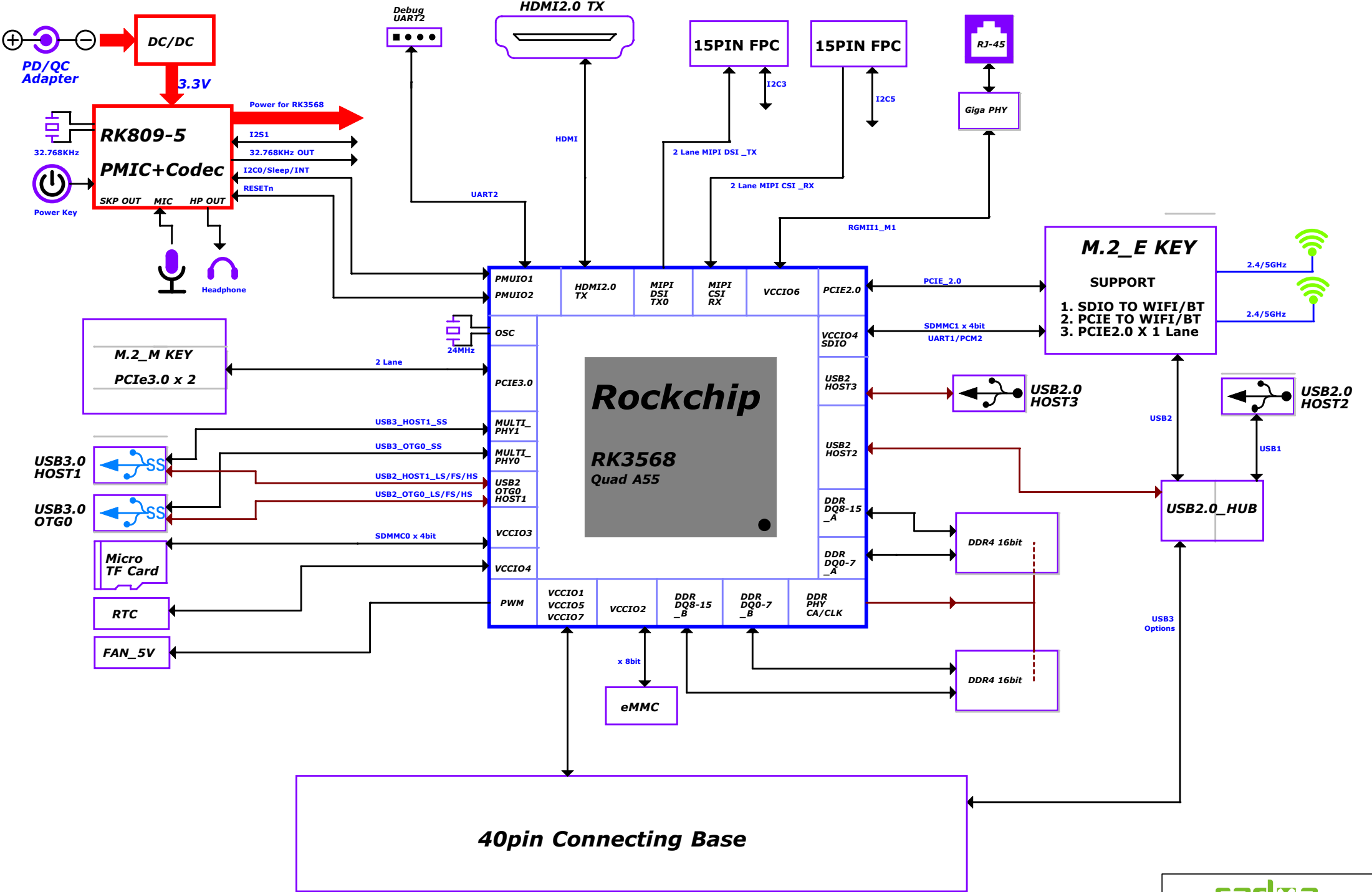
NOTE 2:

Please use our recommended components to avoid too many changes.
For more informations about the second source,please refer to our AVL.

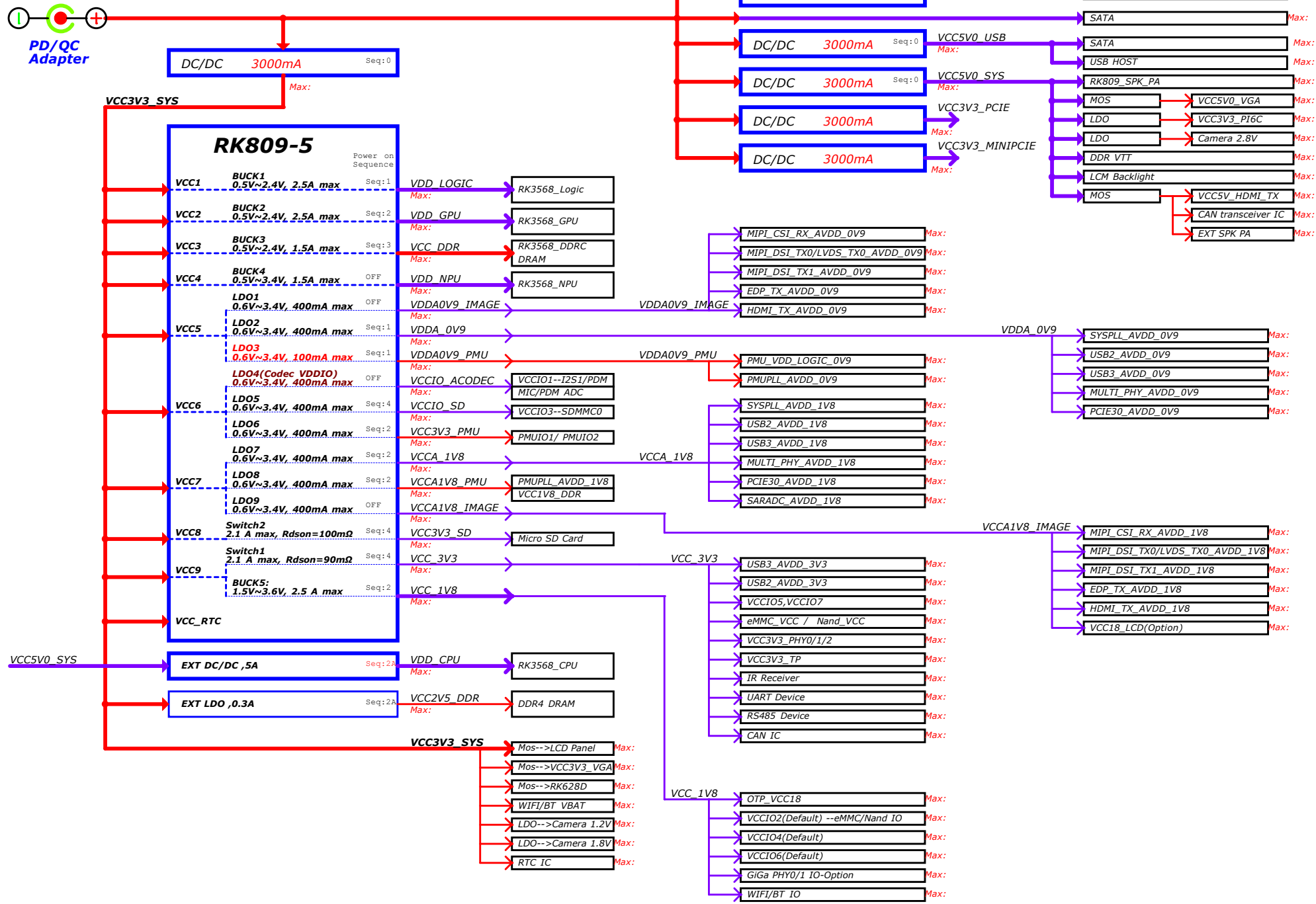
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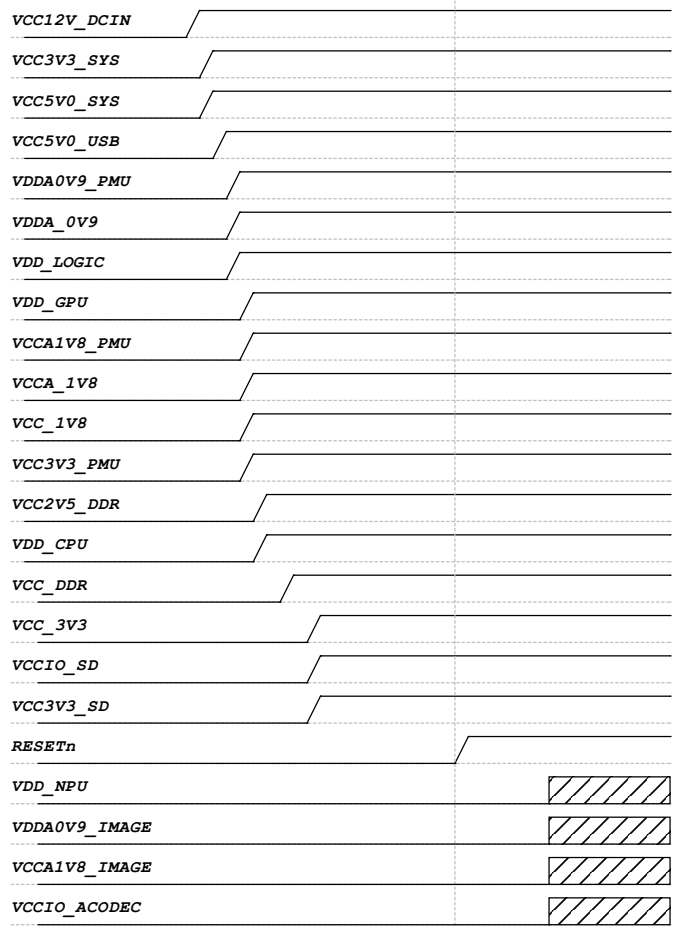
Gong Le Ref Block Diagram



Default Power Diagram



Power Sequence




Power Supply	PMIC Channel	Supply Limit	Power Name	Time Slot	Default Voltage	Default ON/OFF	Work Voltage	Peak Current	Sleep Current
VCC3V3_SYS	RK809_BUCK1	2.5A	VDD_LOGIC	Slot:1	0.9V	ON	0.9V	TBD	TBD
VCC3V3_SYS	RK809_BUCK2	2.5A	VDD_GPU	Slot:2	0.9V	ON	DVFS	TBD	TBD
VCC3V3_SYS	RK809_BUCK3	1.5A	VCC_DDR	Slot:3	ADJ FB=0.8V	ON	1.2V (DDR4)	TBD	TBD
VCC3V3_SYS	RK809_BUCK4	1.5A	VDD_NPU	N/A	0V	OFF	DVFS	TBD	TBD
VCC3V3_SYS	RK809_LDO1	0.4A	VDDA0V9_IMAGE	N/A	0V	OFF	0.9V	TBD	TBD
	RK809_LDO2	0.4A	VDDA_0V9	Slot:1	0.9V	ON	0.9V	TBD	TBD
	RK809_LDO3	0.1A	VDDA0V9_PMU	Slot:1	0.9V	ON	0.9V	TBD	TBD
VCC3V3_SYS	RK809_LDO4	0.4A	VCCIO_ACODEC	N/A	0V	OFF	3.3V	TBD	TBD
	RK809_LDO5	0.4A	VCCIO_SD	Slot:4	3.3V	ON	3.3V or 1.8V (VCC3V3_PMU)	TBD	TBD
	RK809_LDO6	0.4A	VCC3V3_PMU	Slot:2	3.3V	ON	3.3V	TBD	TBD
VCC3V3_SYS	RK809_LDO7	0.4A	VCCA_1V8	Slot:2	1.8V	ON	1.8V	TBD	TBD
	RK809_LDO8	0.4A	VCCA1V8_PMU	Slot:2	1.8V	ON	1.8V	TBD	TBD
VCC3V3_SYS	RK809_LDO9	0.4A	VCCA1V8_IMAGE	N/A	0V	OFF	1.8V	TBD	TBD
	RK809_SW2 100mohm	2.1A	VCC3V3_SD	Slot:4	3.3V	ON	3.3V	TBD	TBD
VCC3V3_SYS	RK809_SW1 90mohm	2.1A	VCC_3V3	Slot:4	3.3V	ON	3.3V	TBD	TBD
	RK809_BUCK5	2.5A	VCC_1V8	Slot:2	1.8V	ON	1.8V	TBD	TBD
	RK809_RESETh			Slot:4+5					
VCC12V_DCIN	EXT BUCK	3.0A	VCC3V3_SYS	Slot:0	3.3V	ON	3.3V	TBD	TBD
VCC12V_DCIN	EXT BUCK	3.0A	VCC5V0_SYS	Slot:0	5.0V	ON	5.0V	TBD	TBD
VCC5V0_SYS	EXT BUCK	6.0A	VDD_CPU	Slot:2A	1.025V	ON	DVFS	TBD	TBD
VCC3V3_SYS	EXT LDO	0.3A	VCC2V5_DDR	Slot:2A	2.5V	ON	2.5V	TBD	TBD

Default IO Power Domain Map

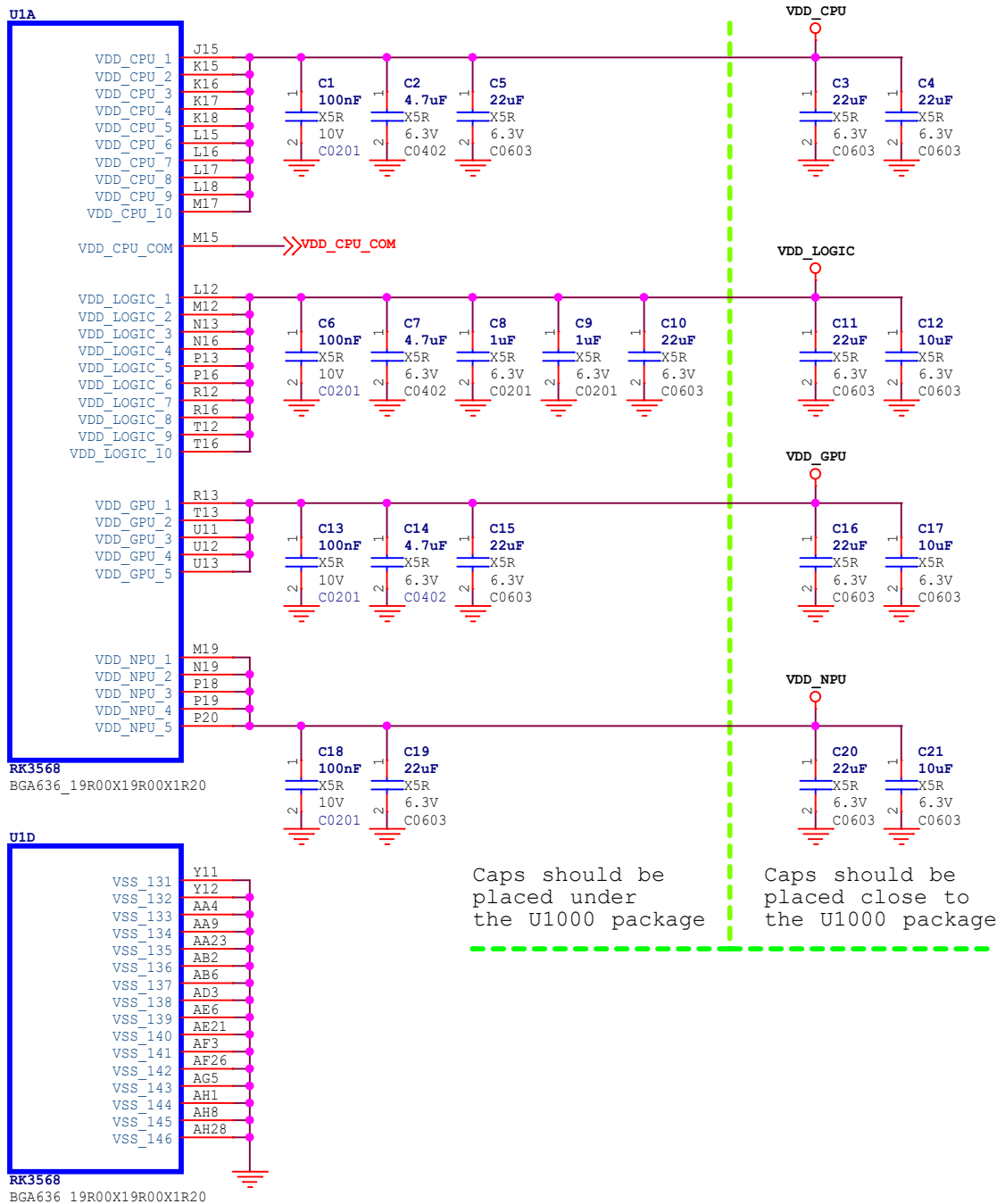
IO Domain	Pin Num	Support IO Voltage		Actual assigned IO Domain Voltage			Notes
		3.3V	1.8V	Supply Power Net Name	Power Source	Voltage	
PMUIO1	Pin Y20	✓	✗	VCC3V3_PMU	VCC3V3_PMU	3.3V	
PMUIO2	Pin W19	✓	✓	VCC3V3_PMU	VCC3V3_PMU	3.3V	
VCCIO1	Pin H17	✓	✓	VCCIO_ACODEC	VCCIO_ACODEC	3.3V	
VCCIO2	Pin H18	✓	✓	VCCIO_FLASH	VCC_1V8	1.8V	PIN "FLASH_VOL_SEL" must be logic High if VCCIO_FLASH=3.3V, FLASH_VOL_SEL must be logic low
VCCIO3	Pin L22	✓	✓	VCCIO_SD	VCCIO_SD	3.3V	
VCCIO4	Pin J21	✓	✓	VCCIO4	VCC_1V8	1.8V	
VCCIO5	Pin V10 Pin V11	✓	✓	VCCIO5	VCC_3V3	3.3V	
VCCIO6	Pin R9 Pin U9	✓	✓	VCCIO6	VCC_1V8	1.8V	
VCCIO7	Pin V12	✓	✓	VCCIO7	VCC_3V3	3.3V	

If the power domain voltage is adjusted, the software configuration must be updated synchronously, other wise the IO may be damaged!



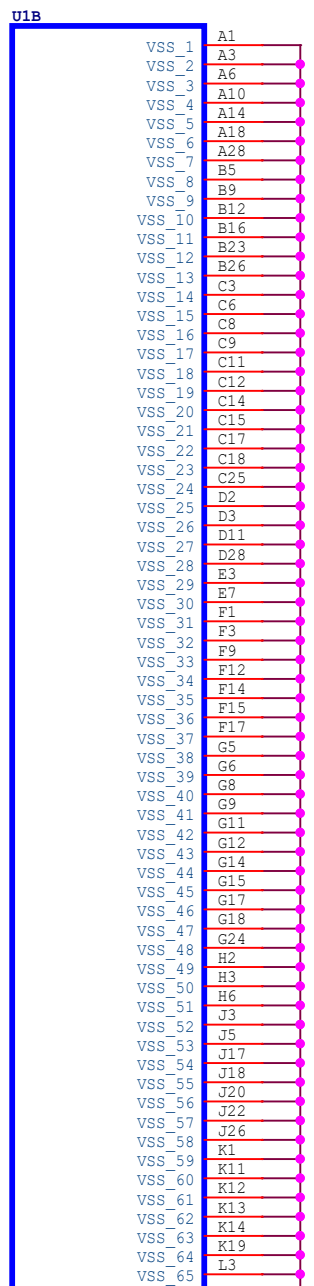
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A3	Page Name: Power Sequence/IO Domain Map	V1.3
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RK3568_ABCDE (Power&Gnd)

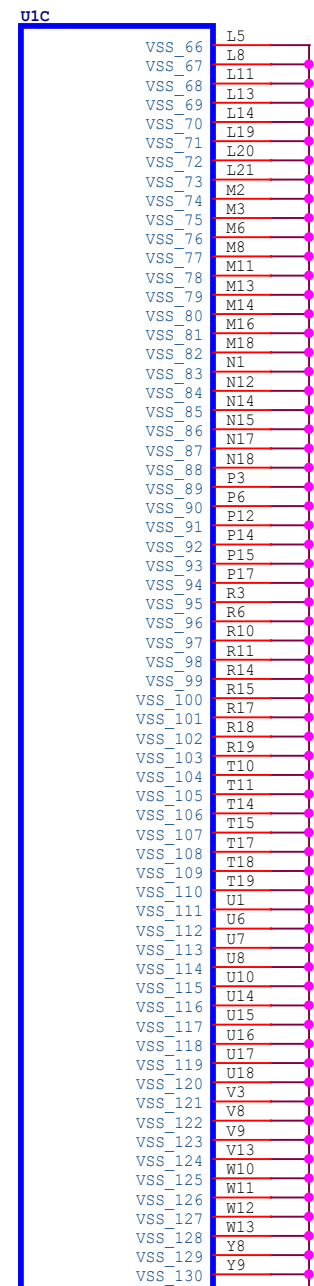


Caps should be placed under the U1000 package

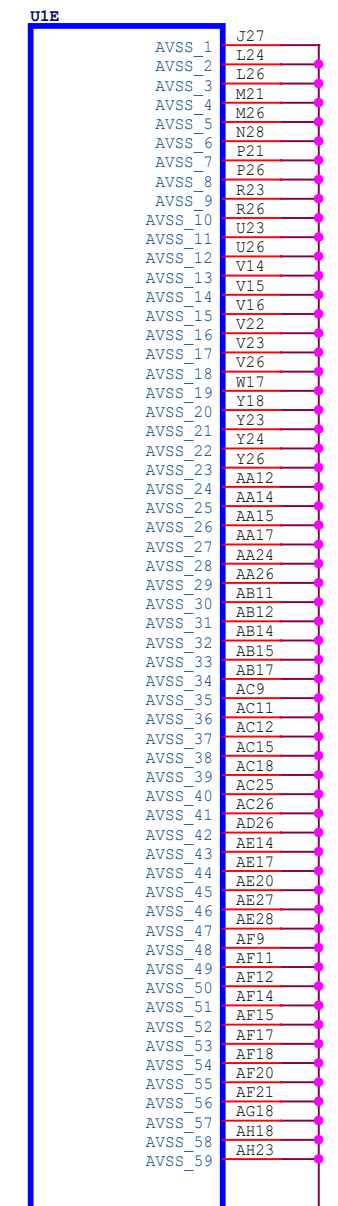
Caps should be placed close to the U1000 package



RK3568 BGA636_19R00X19R00X1R20



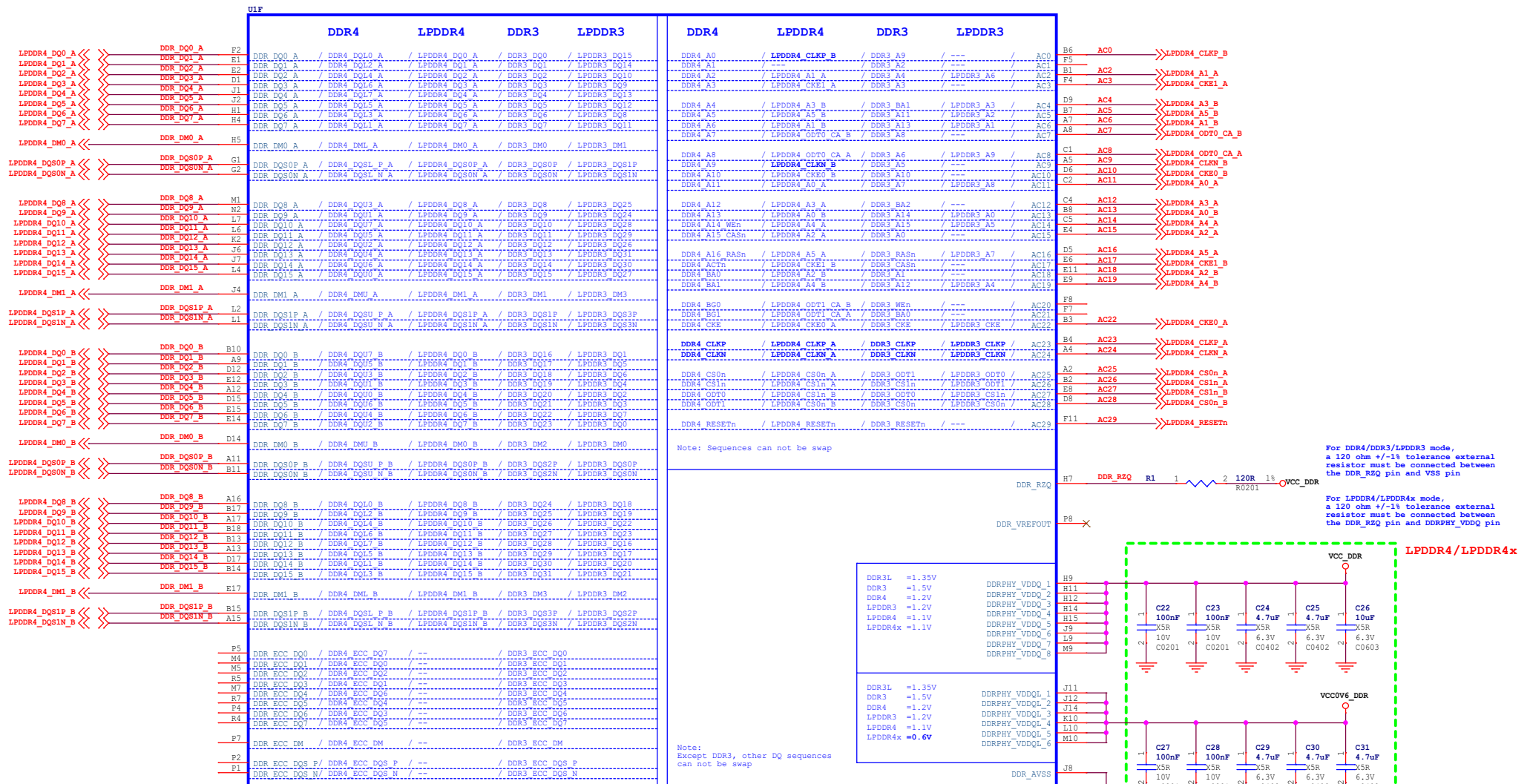
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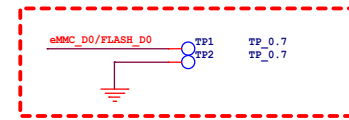
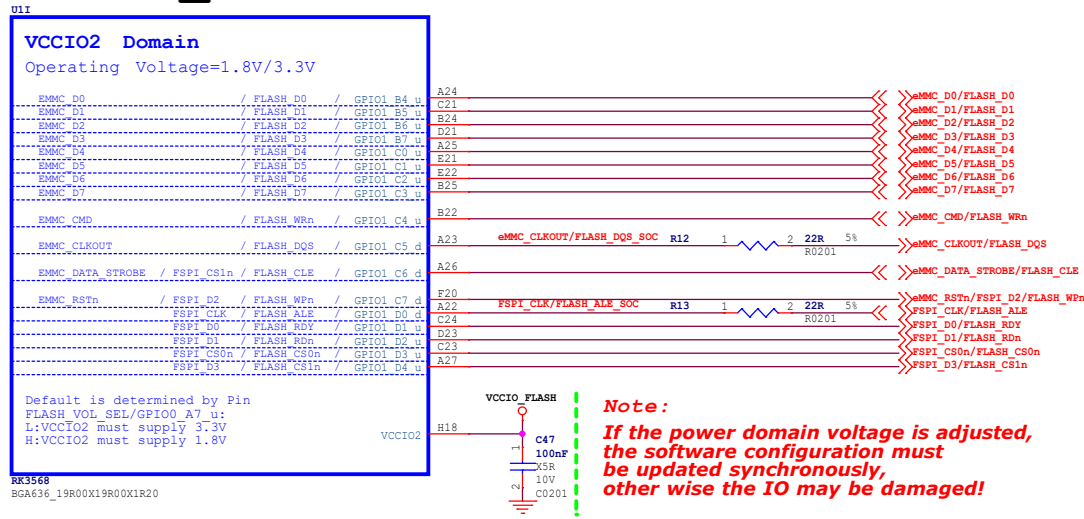
RK3568 BGA636_19R00X19R00X1R20



RK3568_F (DDR PHY)

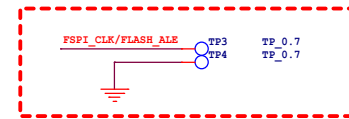


RK3568_I (VCCIO2 Domain)



Note:
For eMMC or Nand Flash:
If eMMC_D0/FLASH_D0=0V at after power on and reset, then system will enter into Maskrom mode.

Layout note:
Test point must be placed on the line, and no branch can be added



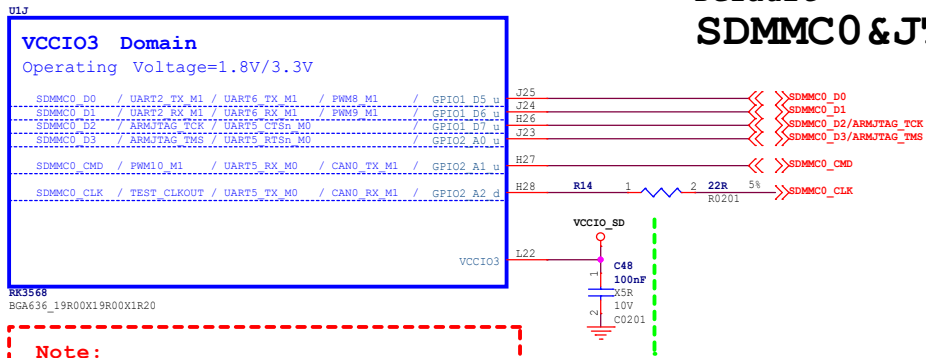
Note:
For SPI Flash:
If FSPI_CLK=0V at after power on and reset, then system will enter into Maskrom mode.

Note:
Reserve TestPoint for put the system into Maskrom mode to update the firmware
When writing mismatched firmware or other conditions result in boot failure, use this test point

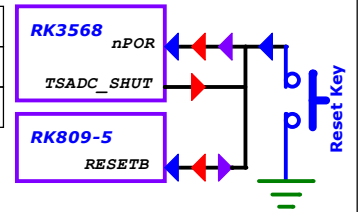
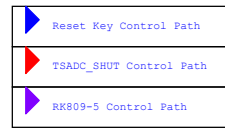
Except in this case, please use Recovery Key
Put the system into loader mode to update the firmware

RK3568_J (VCCIO3 Domain)

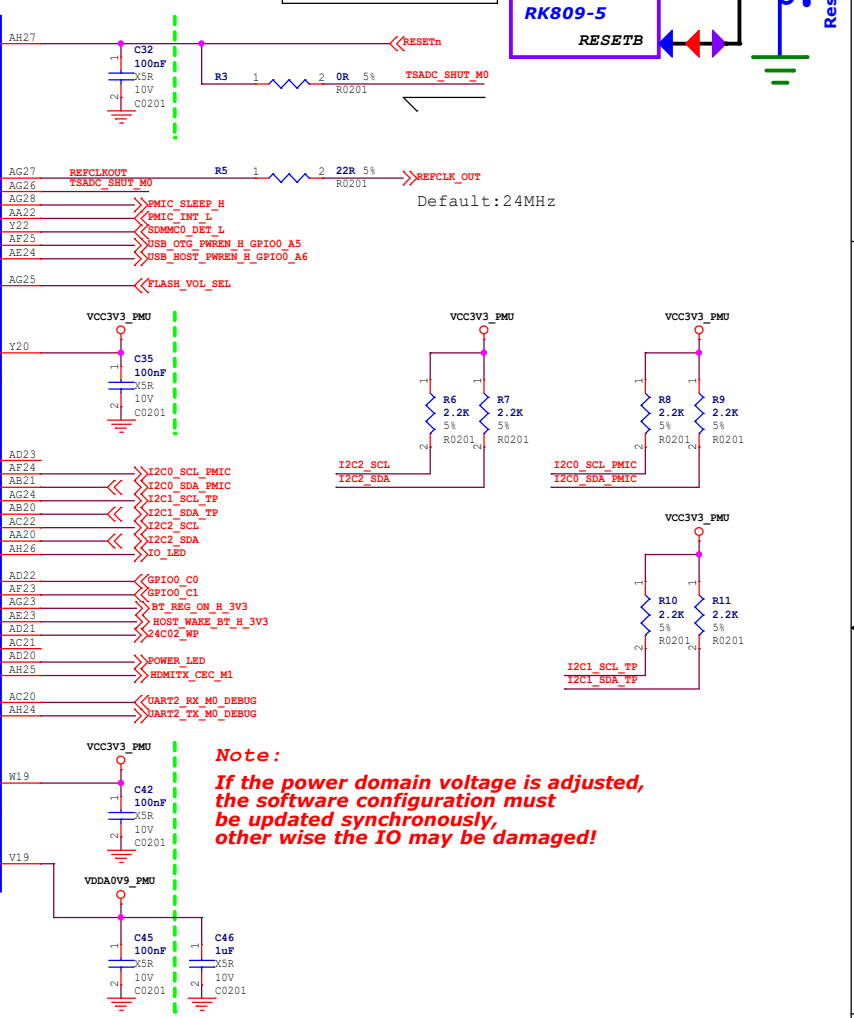
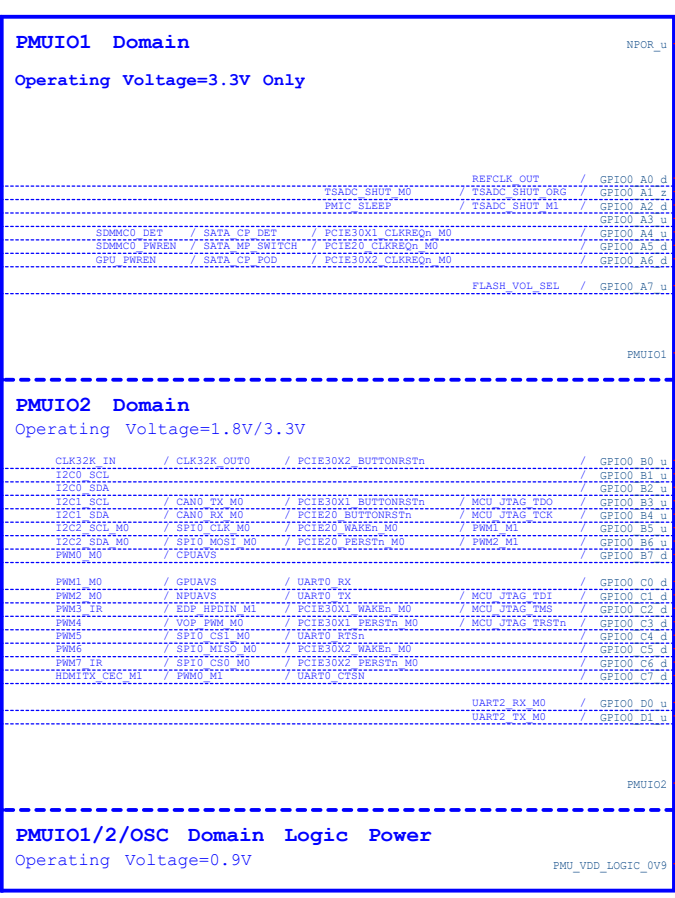
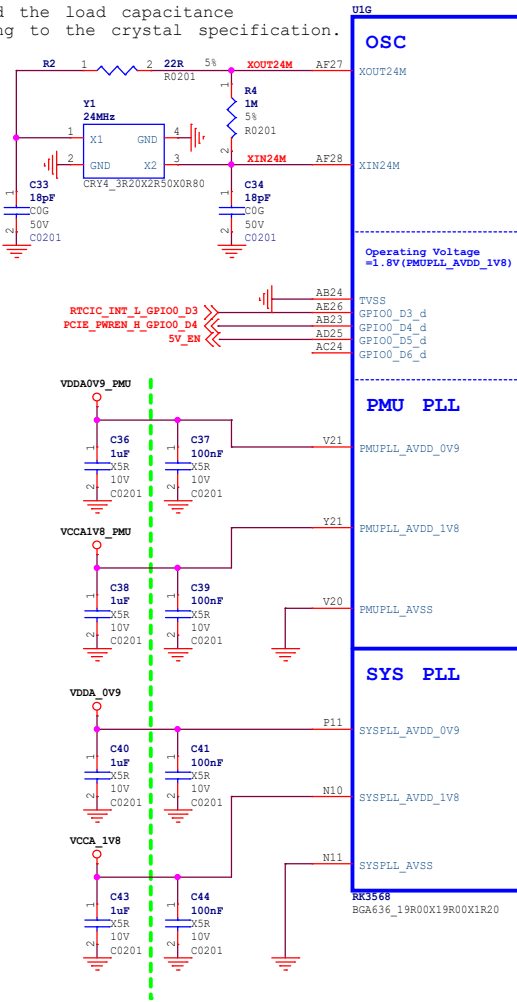
Default SDMMC0 & JTAG



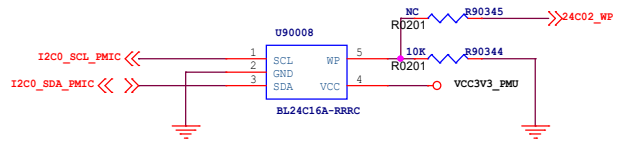
RK3568_G (OSC/PLL/PMUIO1/2)



Note:
Adjusted the load capacitance according to the crystal specification.



Note:
If the power domain voltage is adjusted, the software configuration must be updated synchronously, otherwise the IO may be damaged!



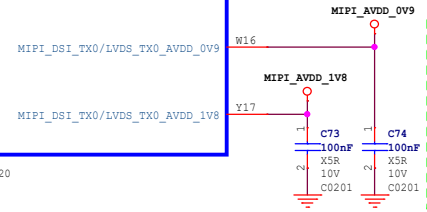
Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package. Other caps should be placed close to the U1000 package

RK3568_R (MIPI_DSI_TX0/LVDS_TX0)

U1R

MIPI DSI TX0/LVDS TX0

MIPI_DSI_TX0_D0P/LVDS_TX0_D0P AH17
MIPI_DSI_TX0_D0N/LVDS_TX0_D0N AG17
MIPI_DSI_TX0_D1P/LVDS_TX0_D1P AH16
MIPI_DSI_TX0_D1N/LVDS_TX0_D1N AG16
MIPI_DSI_TX0_D2P/LVDS_TX0_D2P AH14
MIPI_DSI_TX0_D2N/LVDS_TX0_D2N AG14
MIPI_DSI_TX0_D3P/LVDS_TX0_D3P AH13
MIPI_DSI_TX0_D3N/LVDS_TX0_D3N AG13
MIPI_DSI_TX0_CLKP/LVDS_TX0_CLKP AH15
MIPI_DSI_TX0_CLKN/LVDS_TX0_CLKN AG15



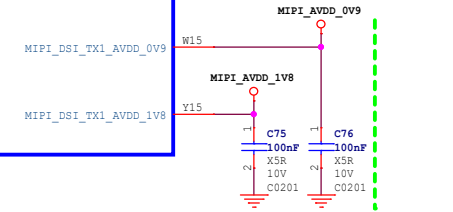
RK3568
BGA636_19R00X19R00X1R20

RK3568_S (MIPI_DSI_TX1)

U1S

MIPI DSI TX1

MIPI_DSI_TX1_D0P AD18
MIPI_DSI_TX1_D0N AE18
MIPI_DSI_TX1_D1P AD17
MIPI_DSI_TX1_D1N AC17
MIPI_DSI_TX1_D2P AD14
MIPI_DSI_TX1_D2N AC14
MIPI_DSI_TX1_D3P AD12
MIPI_DSI_TX1_D3N AE12
MIPI_DSI_TX1_CLKP AD15
MIPI_DSI_TX1_CLKN AE15



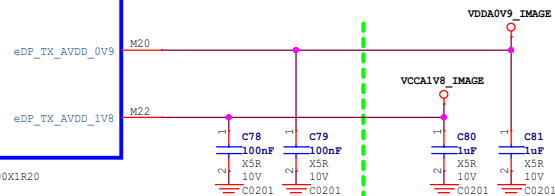
RK3568
BGA636_19R00X19R00X1R20

RK3568_T (eDP TX)

U1T

eDP_TX

eDP_TX_D0P J28
eDP_TX_D0N K27
eDP_TX_D1P K28
eDP_TX_D1N L27
eDP_TX_D2P L28
eDP_TX_D2N M27
eDP_TX_D3P M28
eDP_TX_D3N N27
eDP_TX_AUXP L25
eDP_TX_AUXN M25



RK3568
BGA636_19R00X19R00X1R20

Note:

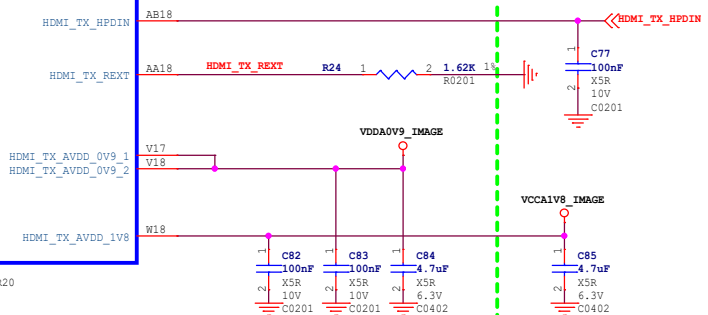
Caps of between dashed green lines and U1000 should be placed under the U1000 package. Other caps should be placed close to the U1000 package.

RK3568_Q (HDMI2.0 TX)

U1Q

HDMI2.0 TX

HDMI_TX_D2P AG22
HDMI_TX_D2N AH22
HDMI_TX_D1P AG21
HDMI_TX_D1N AH21
HDMI_TX_D0P AG20
HDMI_TX_D0N AH20
HDMI_TX_CLKP AH19
HDMI_TX_CLKN AG19



RK3568
BGA636_19R00X19R00X1R20



RK3568_L (VCCIO5 Domain)

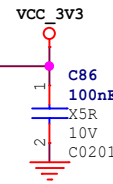
U1L

VCCIO5 Domain

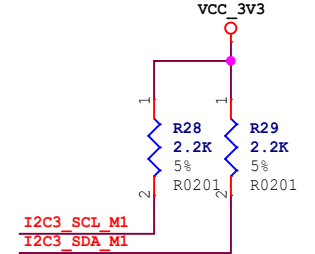
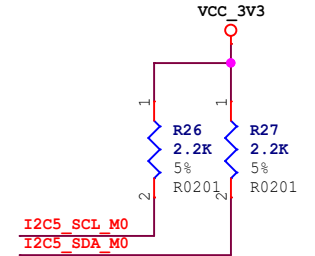
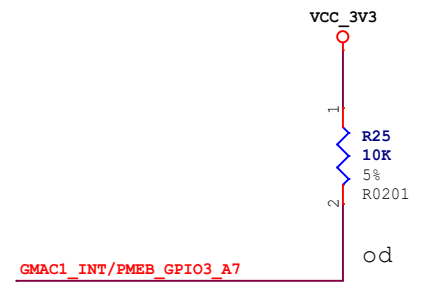
Operating Voltage=1.8V/3.3V

LCDC D0	/ VOP BT656 D0 M0	/ SPI0 MISO M1	/ PCIE20 CLKREQn M1	/ I2S1 MCLK M2	/ GPIO2 D0 d	AG6	<<PCIE20_CLKREQn_M1
LCDC D1	/ VOP BT656 D1 M0	/ SPI0 MOSI M1	/ PCIE20 WAKEn M1	/ I2S1 SCLK TX M2	/ GPIO2 D1 d	AD7	<<PCIE20_WAKEn_M1
LCDC D2	/ VOP BT656 D2 M0	/ SPI0 CS0 M1	/ PCIE30X1 CLKREQn M1	/ I2S1 LRCK TX M2	/ GPIO2 D2 d	AC8	<<HP_DET_L_GPIO2_D2
LCDC D3	/ VOP BT656 D3 M0	/ SPI0 CLK M1	/ PCIE30X1 WAKEn M1	/ I2S1 SDIO M2	/ GPIO2 D3 d	AC7	<<GMAC1_INT/PMEB_GPIO3_A7
LCDC D4	/ VOP BT656 D4 M0	/ SPI2 CS1 M1	/ PCIE30X2 CLKREQn M1	/ I2S1 SDI1 M2	/ GPIO2 D4 d	AF5	<<PCIE30X2_CLKREQn_M1
LCDC D5	/ VOP BT656 D5 M0	/ SPI2 CS0 M1	/ PCIE30X2 WAKEn M1	/ I2S1 SDI2 M2	/ GPIO2 D5 d	AF6	<<PCIE30X2_WAKEn_M1
LCDC D6	/ VOP BT656 D6 M0	/ SPI2 MOSI M1	/ PCIE30X2 PERSTn M1	/ I2S1 SDI3 M2	/ GPIO2 D6 d	AD6	<<PCIE30X2_PERSTn_M1
LCDC D7	/ VOP BT656 D7 M0	/ SPI2 MISO M1	/ UART8 TX M1	/ I2S1 SDO0 M2	/ GPIO2 D7 d	AH5	<<GPIO2_D7
LCDC CLK	/ VOP BT656 CLK M0	/ SPI2 CLK M1	/ UART8 RX M1	/ I2S1 SDO1 M2	/ GPIO3 A0 d	AH4	<<GPIO3_A0
LCDC D8	/ VOP BT1120 D0	/ SPI1 CS0 M1	/ PCIE30X1 PERSTn M1	/ SDMMC2 D0 M1	/ GPIO3 A1 d	AB8	<<GPIO3_A2
LCDC D9	/ VOP BT1120 D1	/ GMAC1 TXD2 M0	/ I2S3 MCLK M0	/ SDMMC2 D1 M1	/ GPIO3 A2 d	AE5	<<GPIO3_A3
LCDC D10	/ VOP BT1120 D2	/ GMAC1 TXD3 M0	/ I2S3 SCLK M0	/ SDMMC2 D2 M1	/ GPIO3 A3 d	AG4	<<GPIO3_A4
LCDC D11	/ VOP BT1120 D3	/ GMAC1 RXD2 M0	/ I2S3 LRCK M0	/ SDMMC2 D3 M1	/ GPIO3 A4 d	AF4	<<GPIO3_A5
LCDC D12	/ VOP BT1120 D4	/ GMAC1 RXD3 M0	/ I2S3 SDO M0	/ SDMMC2 CMD M1	/ GPIO3 A5 d	AH3	<<GPIO3_A6
LCDC D13	/ VOP BT1120 CLK	/ GMAC1 TXCLK M0	/ I2S3 SDI M0	/ SDMMC2 CLK M1	/ GPIO3 A6 d	AG3	<<GPIO3_A6
LCDC D14	/ VOP BT1120 D5	/ GMAC1 RXCLK M0	/ I2S3 SDI M0	/ SDMMC2 DET M1	/ GPIO3 A7 d	AH2	<<GMAC1_INT/PMEB_GPIO3_A7
LCDC D15	/ VOP BT1120 D6	/ ETH1 REFCLK0 25M M0	/ I2S3 SDO M0	/ SDMMC2 PWREN M1	/ GPIO3 B0 d	AG2	<<GMAC1_RSTn_GPIO3_B0
LCDC D16	/ VOP BT1120 D7	/ GMAC1 RXD0 M0	/ UART4 RX M1	/ PWM8 M0	/ GPIO3 B1 d	AG1	<<PWM_FAN
LCDC D17	/ VOP BT1120 D8	/ GMAC1 RXD1 M0	/ UART4 TX M1	/ PWM9 M0	/ GPIO3 B2 d	AF2	<<GPIO3_B2
LCDC D18	/ VOP BT1120 D9	/ GMAC1 RXDV CRS M0	/ I2C5 SCL M0	/ PDM SDI0 M2	/ GPIO3 B3 d	AF1	<<I2C5_SCL_M0
LCDC D19	/ VOP BT1120 D10	/ GMAC1 RXER M0	/ I2C5 SDA M0	/ PDM SDI1 M2	/ GPIO3 B4 d	AE1	<<I2C5_SDA_M0
LCDC D20	/ VOP BT1120 D11	/ GMAC1 TXD0 M0	/ I2C3 SCL M1	/ PWM10 M0	/ GPIO3 B5 d	AE2	<<I2C3_SCL_M1
LCDC D21	/ VOP BT1120 D12	/ GMAC1 TXD1 M0	/ I2C3 SDA M1	/ PWM11 IR M0	/ GPIO3 B6 d	AE3	<<I2C3_SDA_M1
LCDC D22	/ PWM12 M0	/ GMAC1 TXEN M0	/ UART5 TX M1	/ PDM SDI2 M2	/ GPIO3 B7 d	AD4	<<I2C3_SDA_M1
LCDC D23	/ PWM13 M0	/ GMAC1 MCLKINOUT M0	/ UART5 RX M1	/ PDM SDI3 M2	/ GPIO3 C0 d	AD2	<<LCD0_PWREN_H_GPIO3_C0
LCDC HSYNC	/ VOP BT1120 D13	/ SPI1 MOSI M1	/ PCIE20 PERSTn M1	/ I2S1 SDO2 M2	/ GPIO3 C1 d	AD1	<<PCIE20_PERSTn_M1
LCDC VSYNC	/ VOP BT1120 D14	/ SPI1 MISO M1	/ UART5 TX M1	/ I2S1 SDO3 M2	/ GPIO3 C2 d	AA7	<<GPIO3_C2
LCDC DEN	/ VOP BT1120 D15	/ SPI1 CLK M1	/ UART5 RX M1	/ I2S1 SCLK RX M2	/ GPIO3 C3 d	AC4	<<GPIO3_C3
PWM14 M0	/ VOP PWM M1	/ GMAC1 MDC M0	/ UART7 TX M1	/ PDM CLK1 M2	/ GPIO3 C4 d	AC3	<<GPIO3_C4
PWM15 IR M0	/ SPDF TX M1	/ GMAC1 MDIO M0	/ UART7 RX M1	/ I2S1 LRCK RX M2	/ GPIO3 C5 d	AC2	<<GPIO3_C5

VCCIO5_1
VCCIO5_2



Note:
If the power domain voltage is adjusted, the software configuration must be updated synchronously, other wise the IO may be damaged!

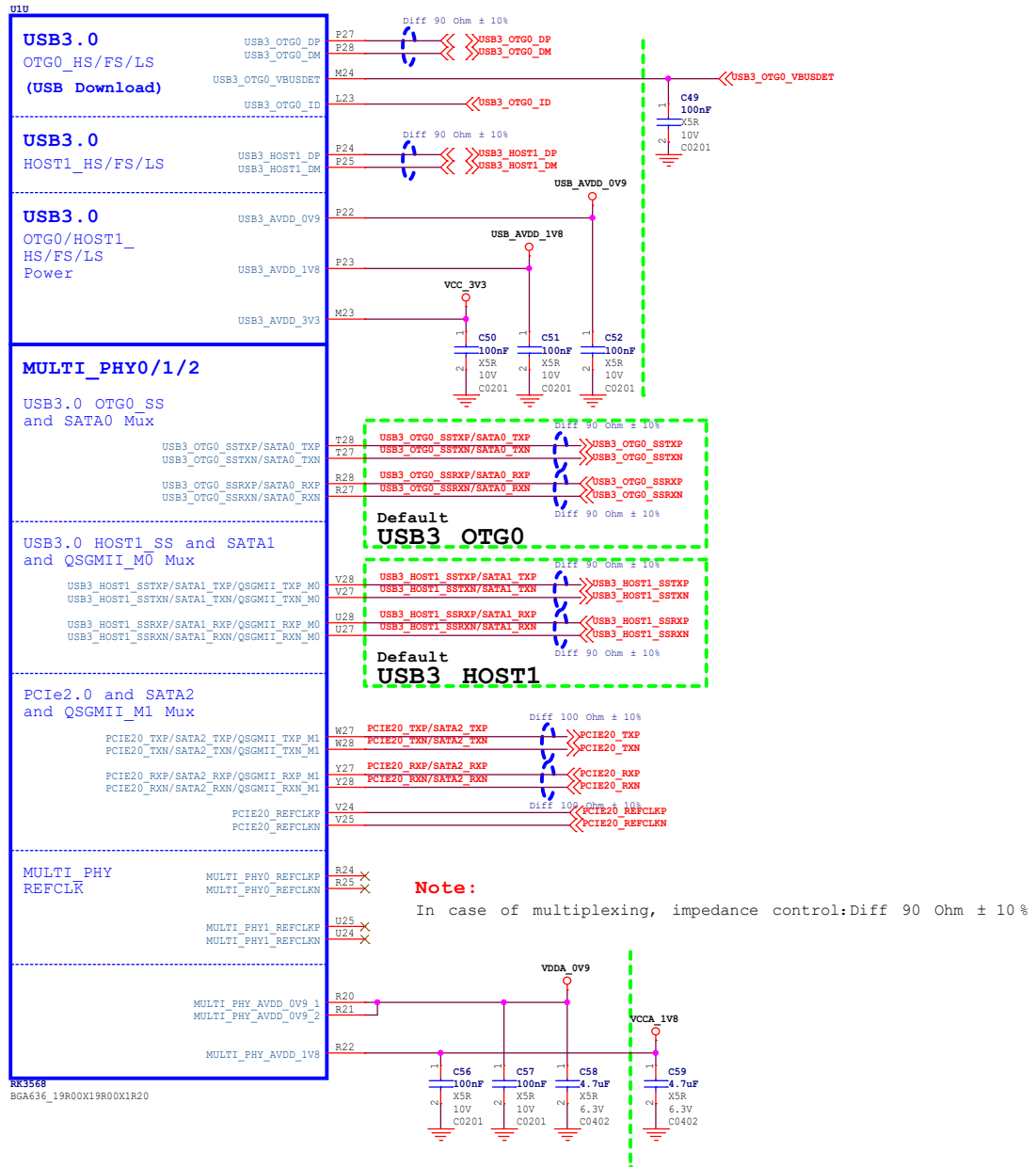


Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package

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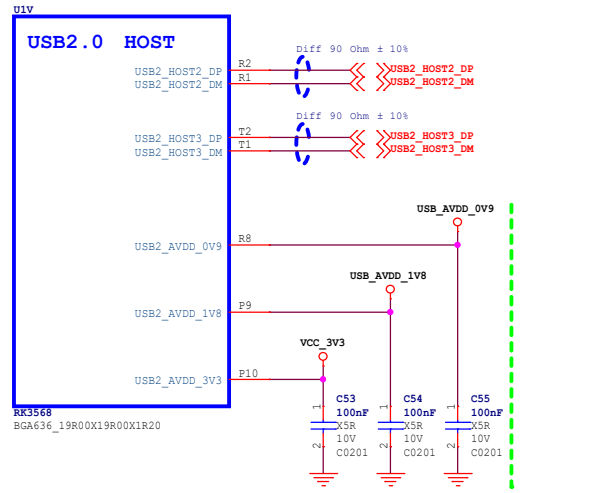
Size	Title:	Gong Le	REV
A4	Page Name:	RK3568_VO Interface_2	V1.3
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RK3568_U (USB3.0/SATA/QSGMII/PCIE2.0 x1)

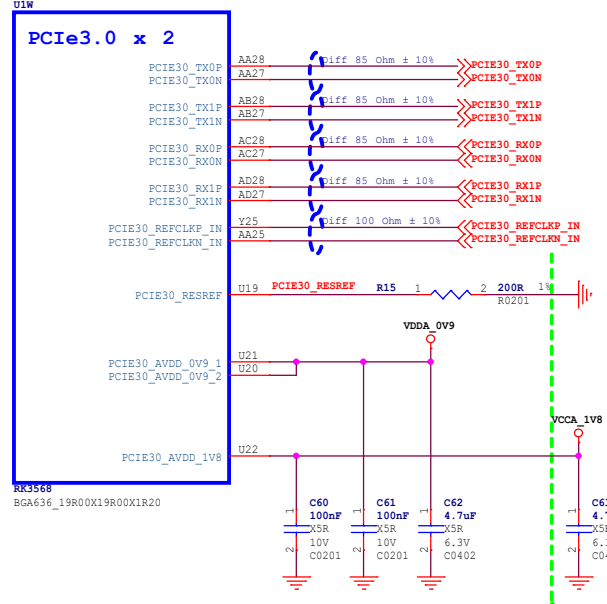


Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package. Other caps should be placed close to the U1000 package

RK3568_V (USB2.0 HOST)

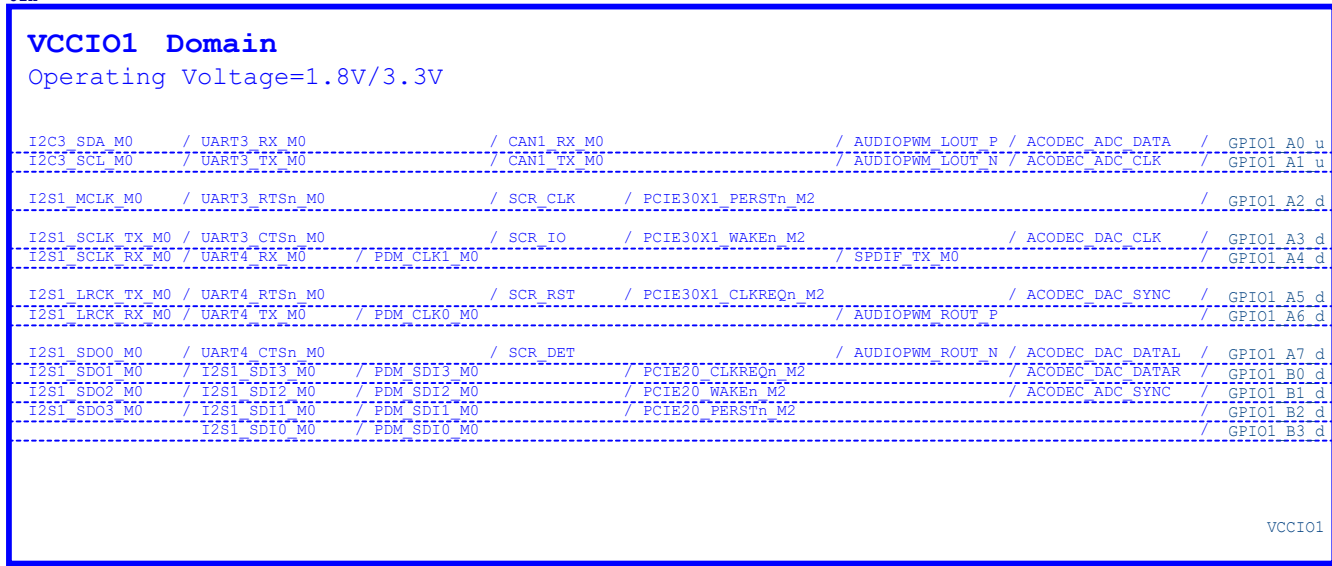


RK3568_W (PCIE3.0 x2)

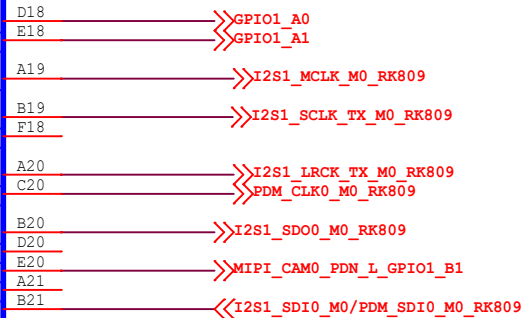


RK3568_H (VCCIO1 Domain)

U1H



RK3568
BGA636_19R00X19R00X1R20



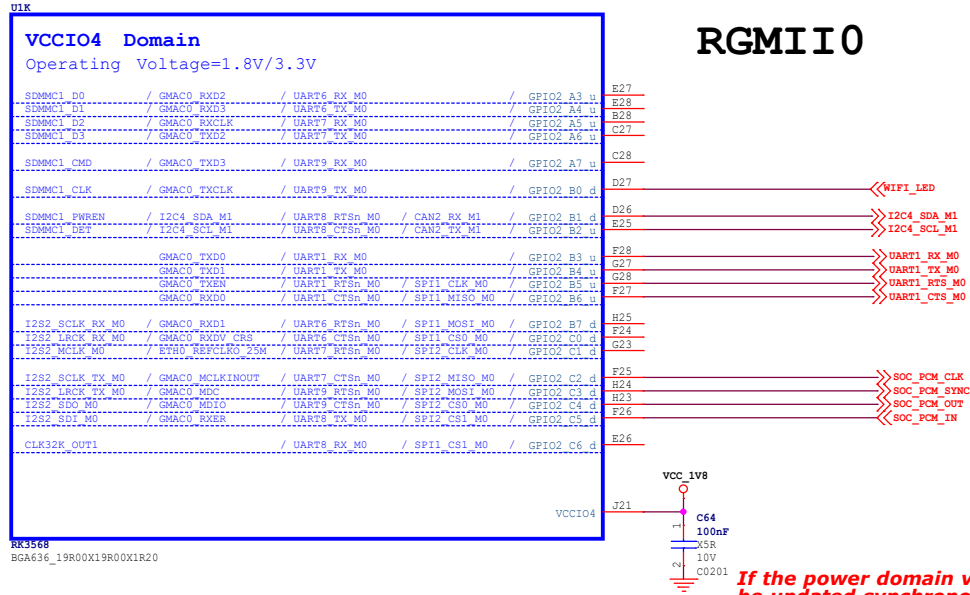
Note:
If the power domain voltage is adjusted, the software configuration must be updated synchronously, otherwise the IO may be damaged!

Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package

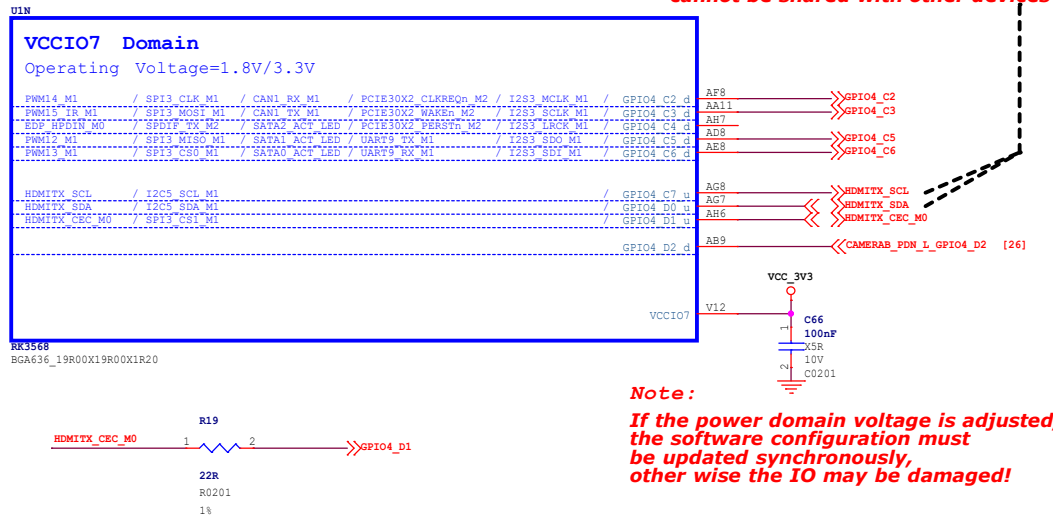


Size	Title: Gong Le	REV
A4	Page Name: RK3568_Audio Interface	V1.3
Date: Tuesday, October 26, 2021 Sheet 13 of 33		

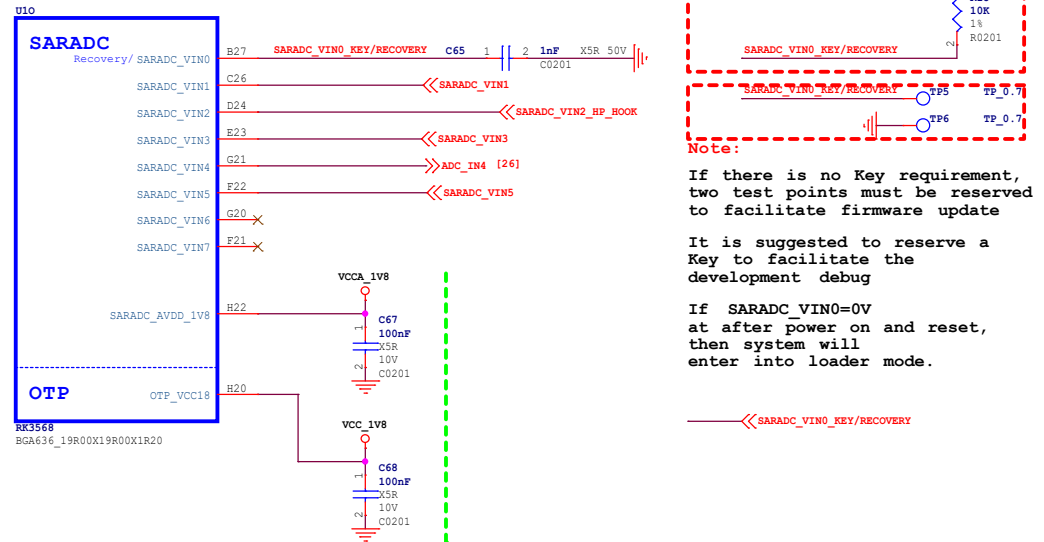
RK3568_K (VCCIO4 Domain)



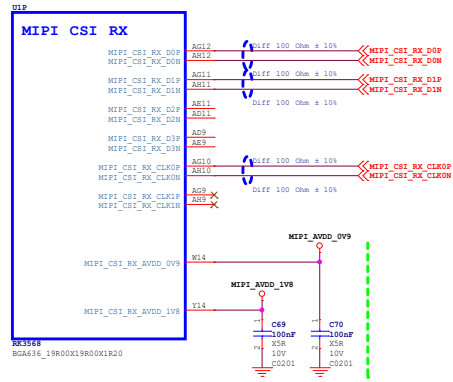
RK3568_N (VCCIO7 Domain)



RK3568_O (SARADC/OTP)

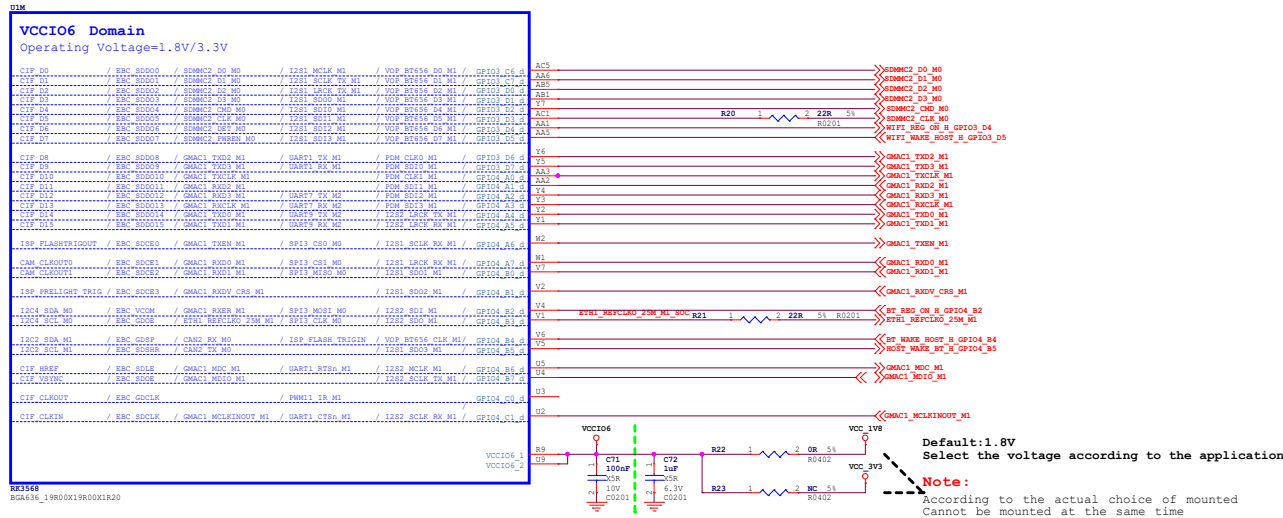


RK3568_P (MIPI_CSI_RX)



Option1	Sensor1 x4Lane	MIPI_CSI_RX_D0-3 MIPI_CSI_RX_CLK0
Option2	Sensor1 x2Lane + Sensor2 x2Lane	MIPI_CSI_RX_D0-1 MIPI_CSI_RX_CLK0 MIPI_CSI_RX_D2-3 MIPI_CSI_RX_CLK1

RK3568_M (VCCIO6 Domain)



Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

Note:
If the power domain voltage is adjusted, the software configuration must be updated synchronously, other wise the IO may be damaged!

Note:
Camera MCLK can select the following clock:
1: CAM_CLKOUT0
2: CAM_CLKOUT1
3: CIF_CLKOUT
4: REFCLK_OUT

Attention to the voltage matching

Mode	16bit	12bit	10bit	8bit
CIF_D0	D0	--	--	--
CIF_D1	D1	--	--	--
CIF_D2	D2	--	--	--
CIF_D3	D3	--	--	--
CIF_D4	D4	D0	--	--
CIF_D5	D5	D1	--	--
CIF_D6	D6	D2	D0	--
CIF_D7	D7	D3	D1	--
CIF_D8	D8	D4	D2	D0
CIF_D9	D9	D5	D3	D1
CIF_D10	D10	D6	D4	D2
CIF_D11	D11	D7	D5	D3
CIF_D12	D12	D8	D6	D4
CIF_D13	D13	D9	D7	D5
CIF_D14	D14	D10	D8	D6
CIF_D15	D15	D11	D9	D7

Support BT601 YCbCr 422 8bit input
Support BT656 YCbCr 422 8bit input
Support RAW 8/10/12bit input
Support BT1120 YCbCr 422 8/10/12/16bit input, single/dual-edge sampling
Support 2/4 mixed BT656/BT1120 YCbCr 422 8bit input

BT1120 16bit Mode:
Default: D0-D7 <--> Y0-Y7, D8-D15 <--> C0-C7
Swap ON: D0-D7 <--> C0-C7, D8-D15 <--> Y0-Y7

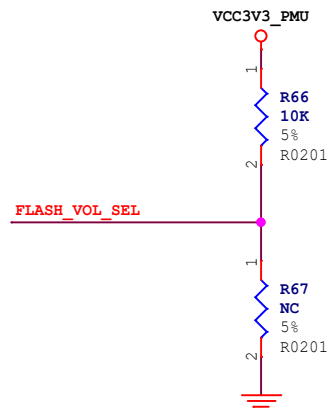
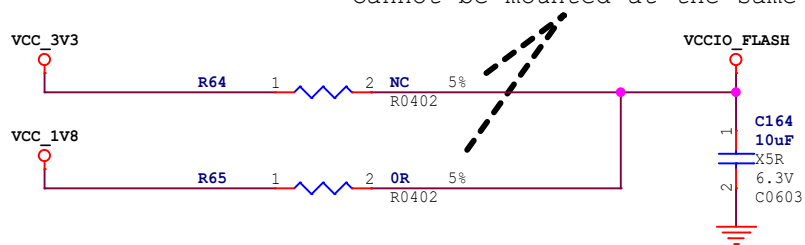
GMAC	Direction	GEPHY	GMAC	Direction	FEPHY
GMACx_TXD0	----->	PHYx_TXD0	GMACx_RXD0	<-----	PHYx_RXD0
GMACx_TXD1	----->	PHYx_TXD1	GMACx_RXD1	<-----	PHYx_RXD1
GMACx_TXD2	----->	PHYx_TXD2			
GMACx_TXD3	----->	PHYx_TXD3			
GMACx_TXEN	----->	PHYx_TXEN	GMACx_RXEN	----->	PHYx_RXEN
GMACx_TXCLK	----->	PHYx_TXCLK			
GMACx_RXD0	<-----	PHYx_RXD0	GMACx_RXD0	<-----	PHYx_RXD0
GMACx_RXD1	<-----	PHYx_RXD1	GMACx_RXD1	<-----	PHYx_RXD1
GMACx_RXD2	<-----	PHYx_RXD2			
GMACx_RXD3	<-----	PHYx_RXD3			
GMACx_RXDV	<-----	PHYx_RXDV	GMACx_RXDV	<-----	PHYx_RXDV
GMACx_RXCLK	<-----	PHYx_RXCLK			
GMACx_RXER	<-----		GMACx_RXER	<-----	PHYx_RXER
GMACx_MDC	----->	PHYx_MDC	GMACx_MDC	----->	PHYx_MDC
GMACx_MDIO	<-----	PHYx_MDIO	GMACx_MDIO	<-----	PHYx_MDIO
ETHx_REFCLK0_25M	<-----	PHYx_XTALIN			
GMACx_MCLKINOUT	<-----	PHYx_XTALIN/REFCLK	GMACx_MCLKINOUT	<-----	PHYx_XTALIN/REFCLK
GPIO	----->	PHYx_RSTn	GPIO	----->	PHYx_RSTn
GPIO	<-----	PHYx_INT/PMEB	GPIO	<-----	PHYx_INT/PMEB

Flash Power Manage

	VCCIO2 domain voltage: Recommend voltage value (VCCIO_FLASH)	FLASH_VOL_SEL state decided to VCCIO2 domain IO driven by default
eMMC	1.8V	FLASH_VOL_SEL --> Logic=H
Nand flash	Default 3.3V, Optional 1.8V	FLASH_VOL_SEL --> Logic=L(Default)
SPI flash	Default 1.8V, Optional 3.3V	FLASH_VOL_SEL --> Logic=H(Default)

Note:

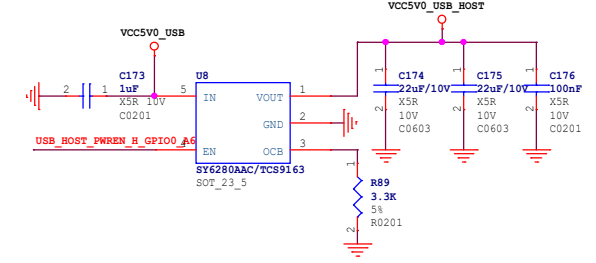
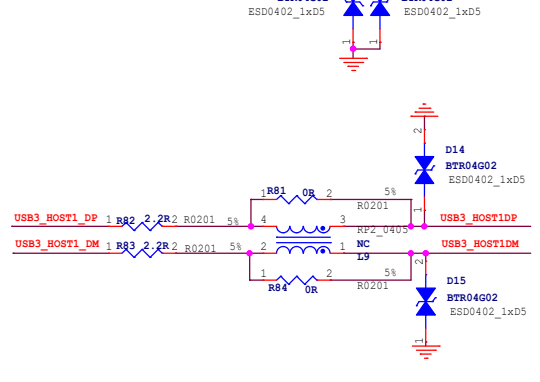
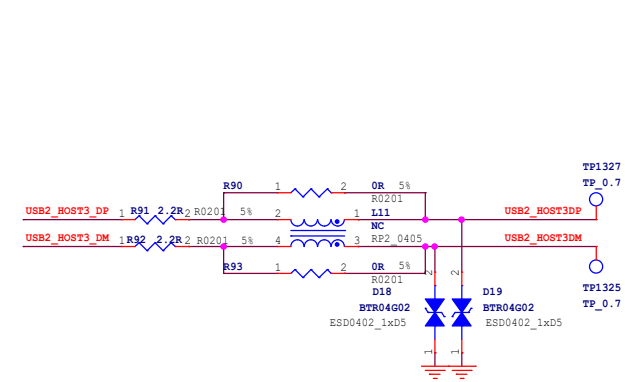
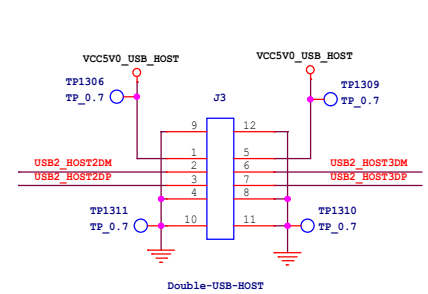
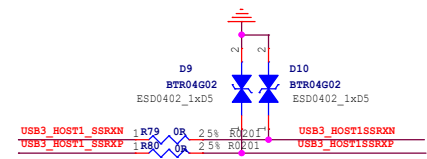
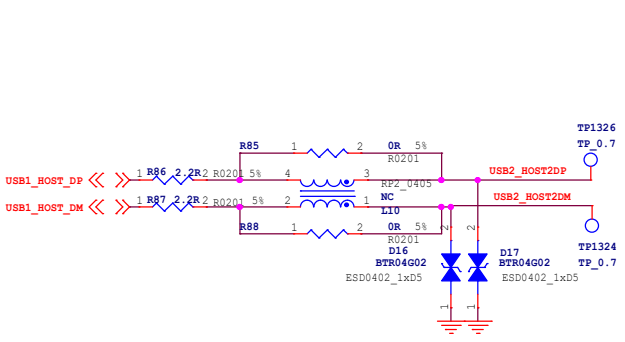
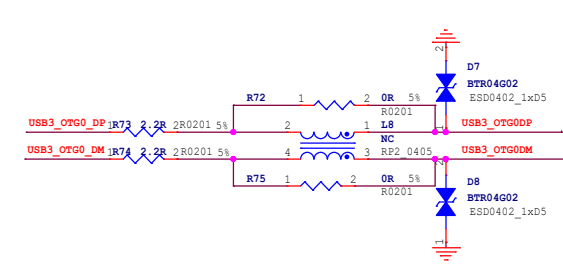
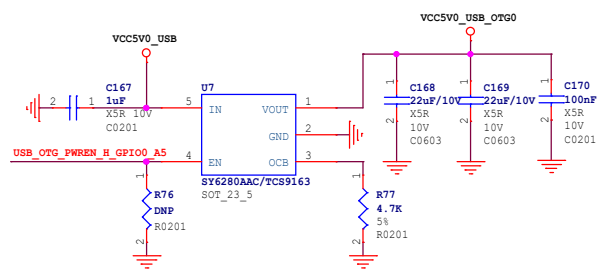
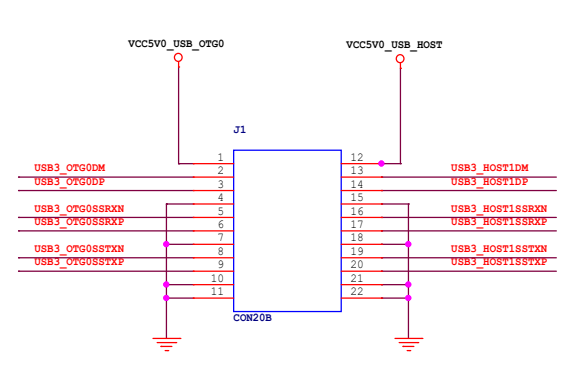
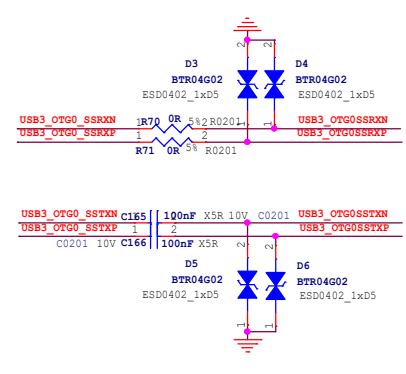
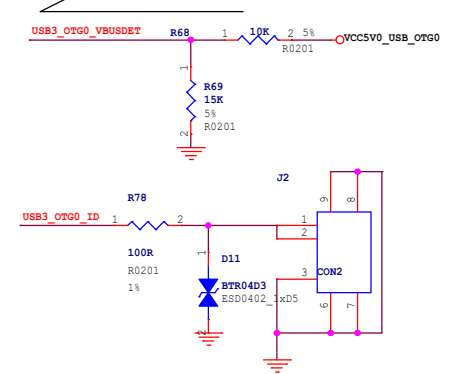
According to the actual choice of mounted
Cannot be mounted at the same time




Note:
FLASH_VOL_SEL state decided
to VCCIO2 domain IO driven by default
Logic=L:3.3V IO driven
Logic=H:1.8V IO driven



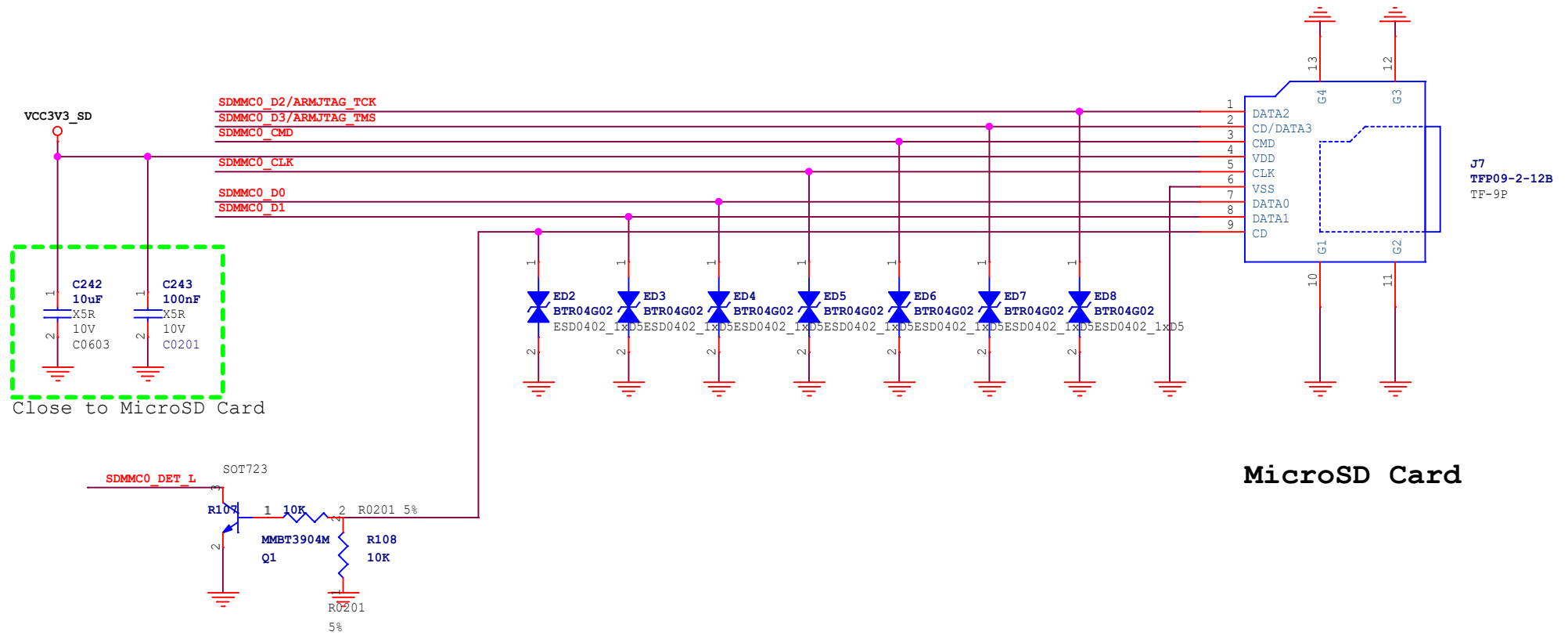
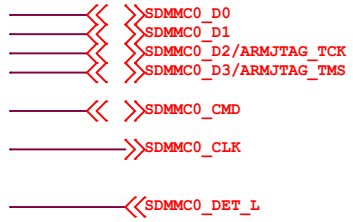
- >> USB3_OTG0_DP
- >> USB3_OTG0_DM
- >> USB3_OTG0_VBUSDET
- >> USB3_OTG0_ID
- >> USB3_OTG0_SSTXP
- >> USB3_OTG0_SSTXN
- >> USB3_OTG0_SSRXN
- >> USB3_OTG0_SSRXP
- >> USB3_OTG0_SSRXN
- >> USB3_HOST1_DP
- >> USB3_HOST1_DM
- >> USB3_HOST1_SSTXP
- >> USB3_HOST1_SSTXN
- >> USB3_HOST1_SSRXP
- >> USB3_HOST1_SSRXN
- >> USB1_HOST_DP
- >> USB1_HOST_DM
- >> USB2_HOST3_DP
- >> USB2_HOST3_DM
- >> USB_OTG_PWREN_H_GPIO0_A5
- >> USB_HOST_PWREN_H_GPIO0_A6





Size	Title: Gong Le	REV
A3	Page Name: USB2/USB3 Port	V1.3
Date: Tuesday, October 26, 2021	Sheet 17 of 33	

MicroSD Card



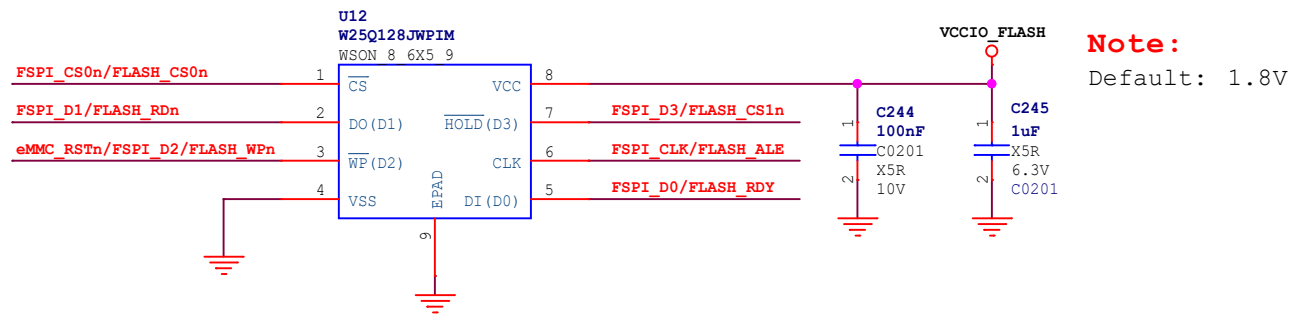
MicroSD Card



Size	Title: Gong Le	REV
A4	Page Name: MicroSD Card	V1.3
Date: Tuesday, October 26, 2021 Sheet 18 of 33		

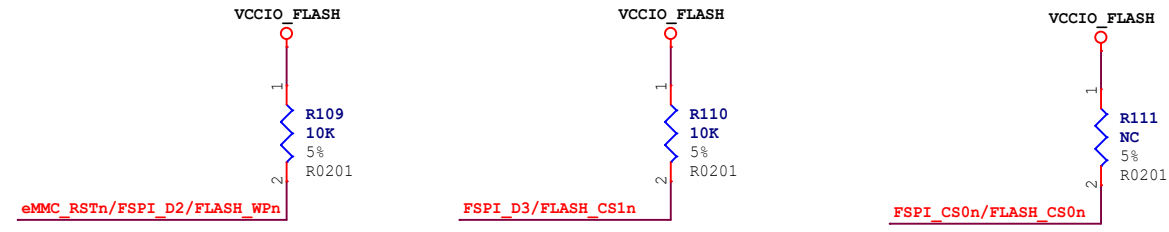
SPI Flash

- >>FSPI_CLK/FLASH_ALE
- >>FSPI_D0/FLASH_RDY
- >>FSPI_D1/FLASH_RDn
- >>eMMC_RSTn/FSPI_D2/FLASH_WPn
- >>FSPI_D3/FLASH_CS1n
- >>FSPI_CS0n/FLASH_CS0n



Note:
Default: 1.8V

Support:
1bit SPI NOR or SPI NAND
4bit SPI NOR or SPI NAND

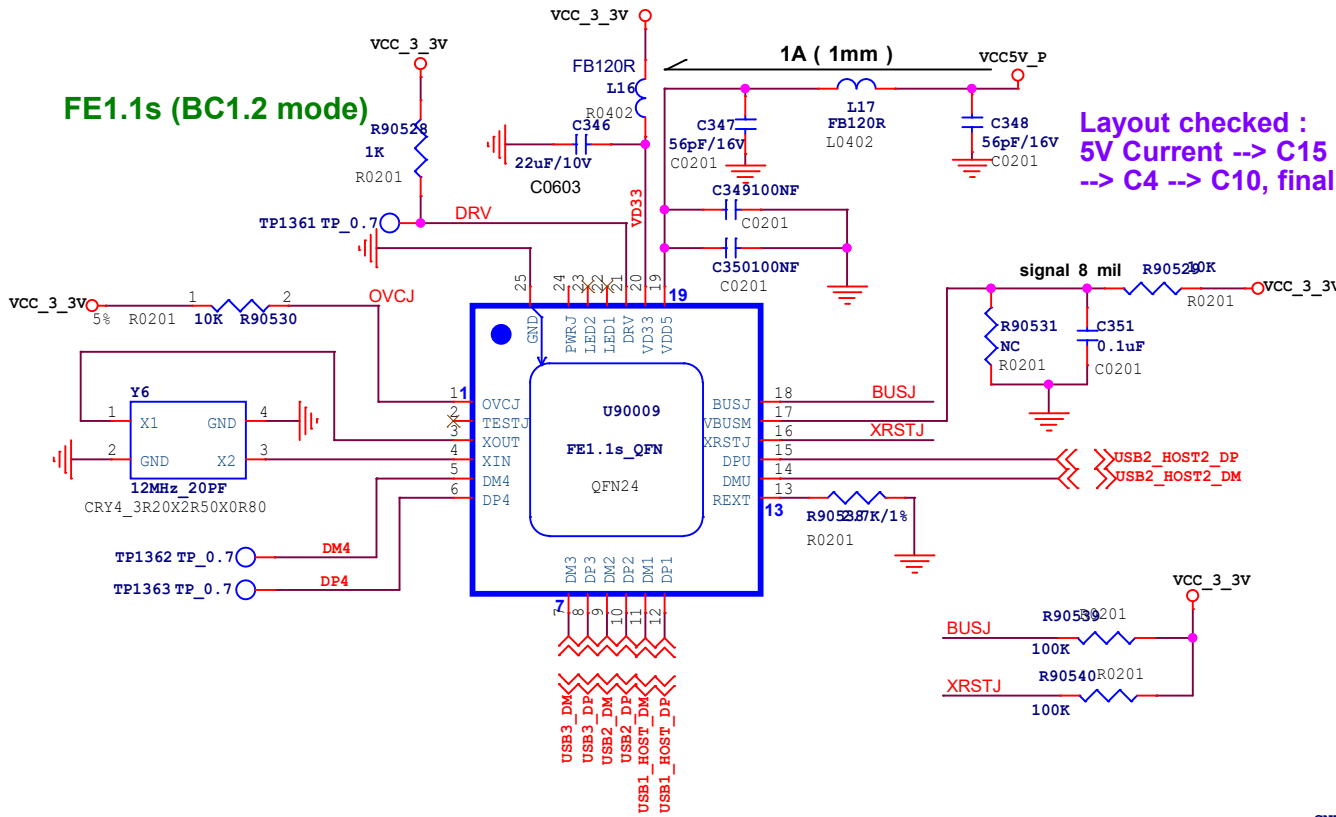


Note:
If Flash is compatible, please notice when eMMC is used, the option is that @eMMC is mounted, @Nand is not mounted, @SPI Flash is not mounted
when Nand is used, the option is that @Nand is mounted, @eMMC is not mounted, @SPI Flash is not mounted
when SPI Flash is used, the option is that SPI Flash is mounted, @eMMC is not mounted, @Nand is not mounted

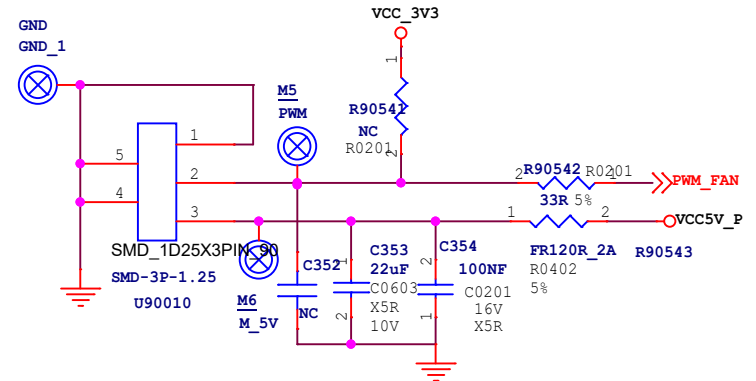
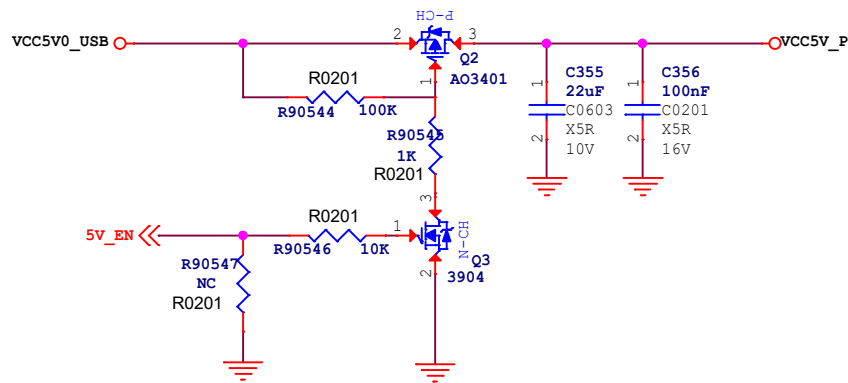
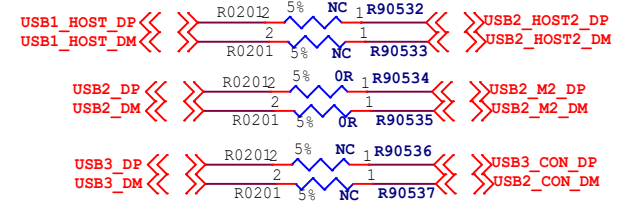


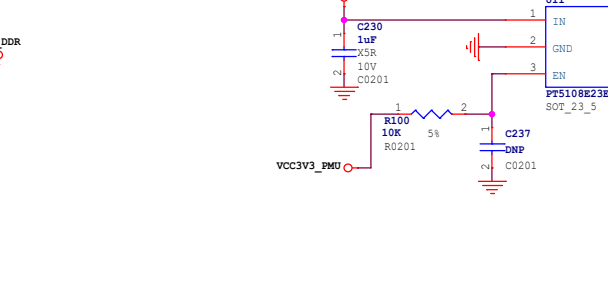
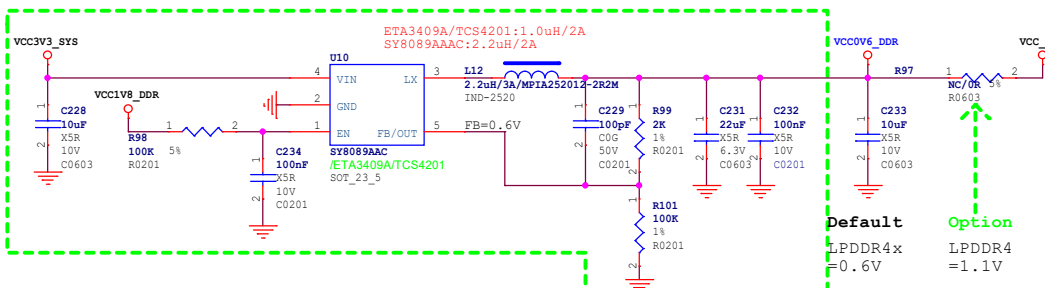
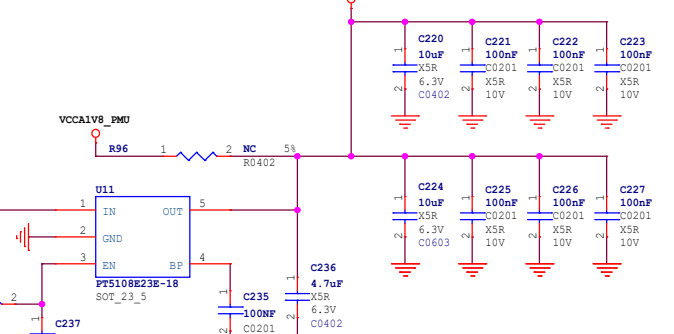
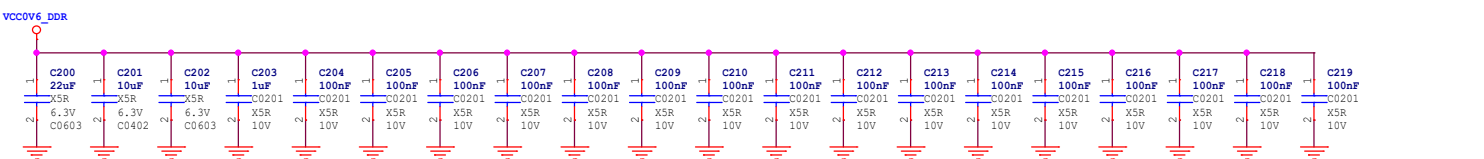
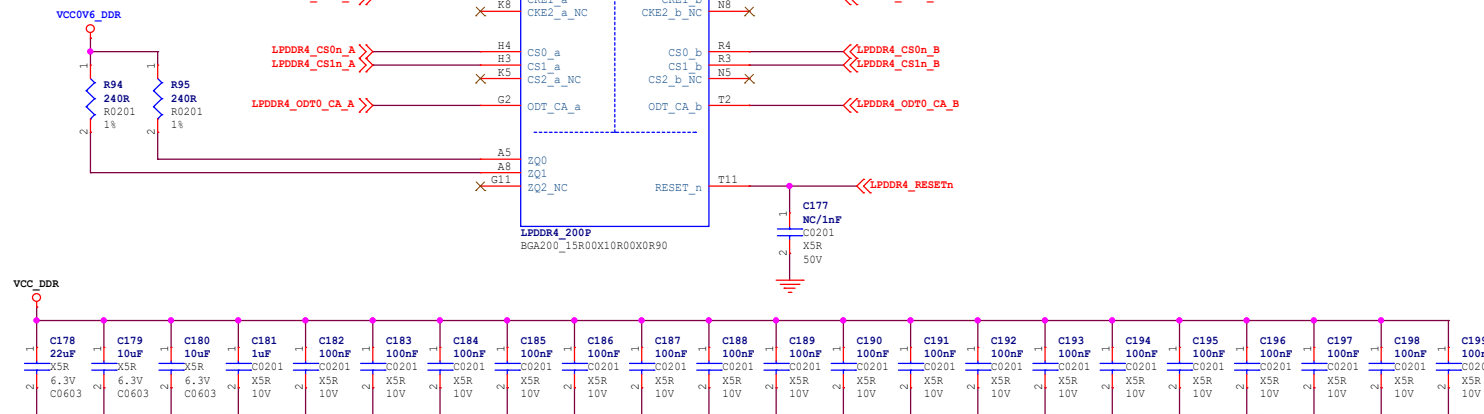
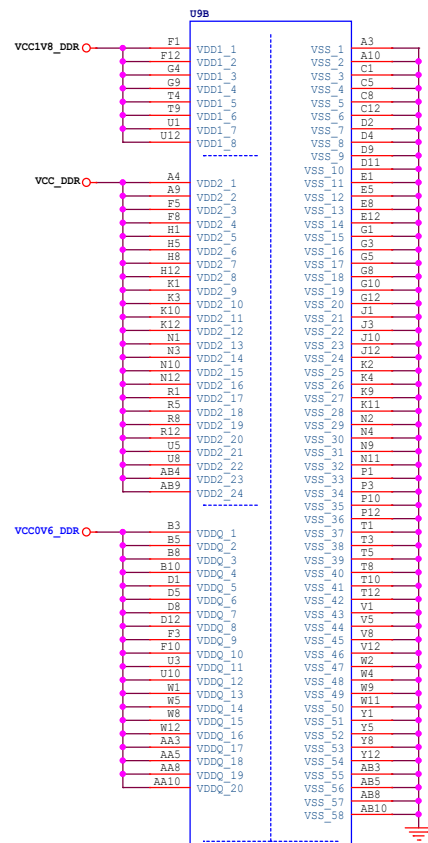
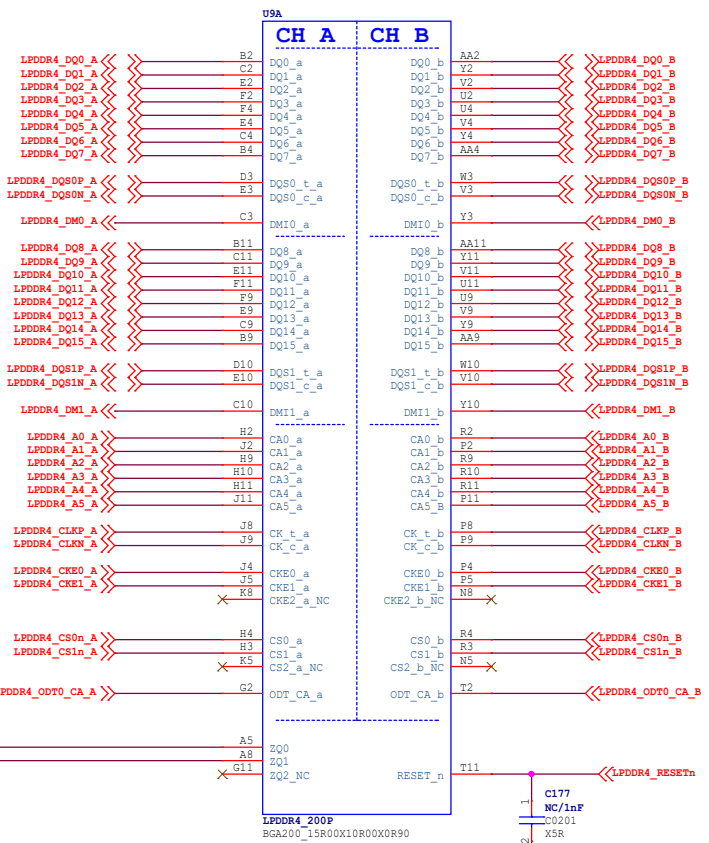
Size	Title: Gong Le	REV
A4	Page Name: SPI FLASH(Optional)	V1.3
Date: Tuesday, October 26, 2021	Sheet 19 of 33	

FE1.1s (BC1.2 mode)



Layout checked :
5V Current -> C15 -> L1 -> C14
-> C4 -> C10, finally to the pin 20 (VDD5).

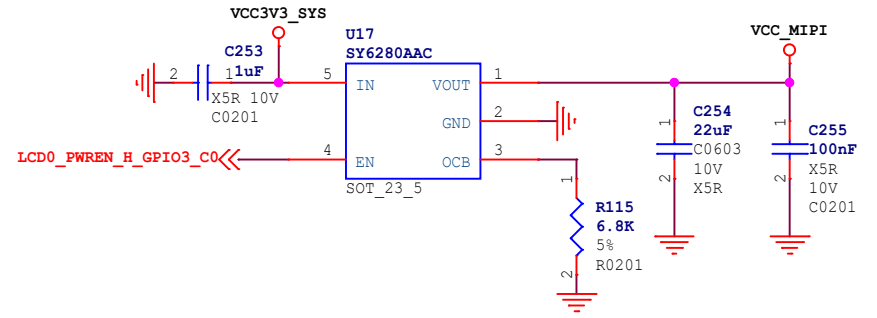
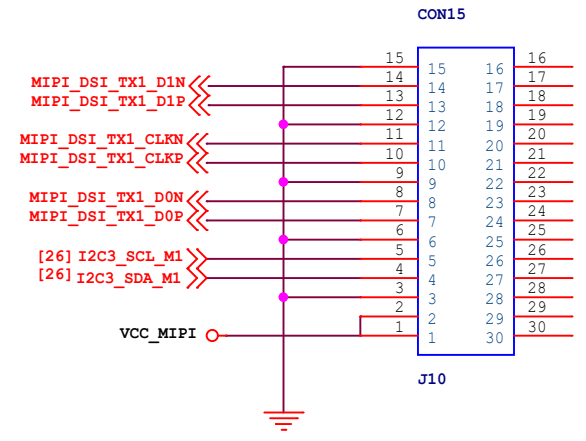
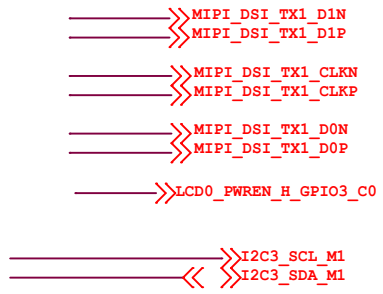




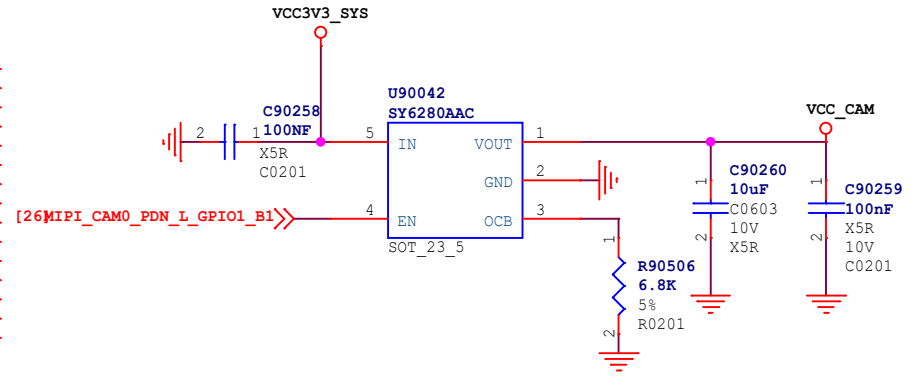
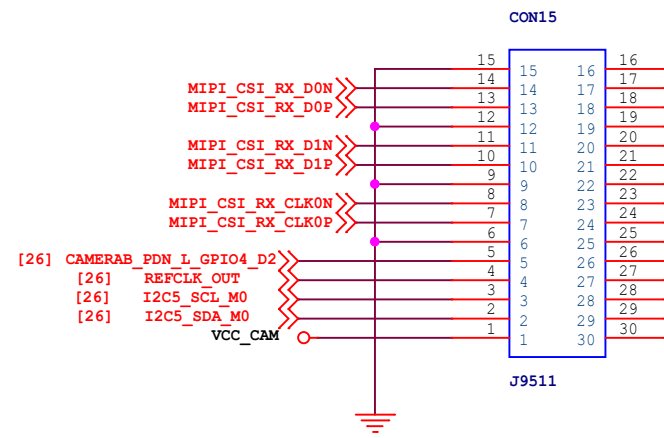
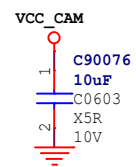
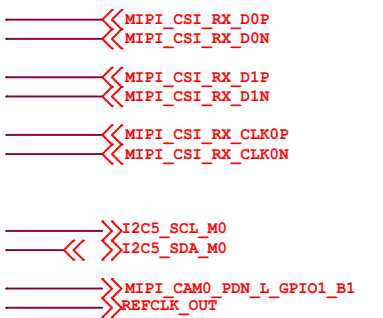
radxa

Size	Title: Gong Le	REV
A3	Page Name: LPDDR4X_1X32bit_200P	V1.3
Date: Tuesday, October 26, 2021	Sheet	21 of 33

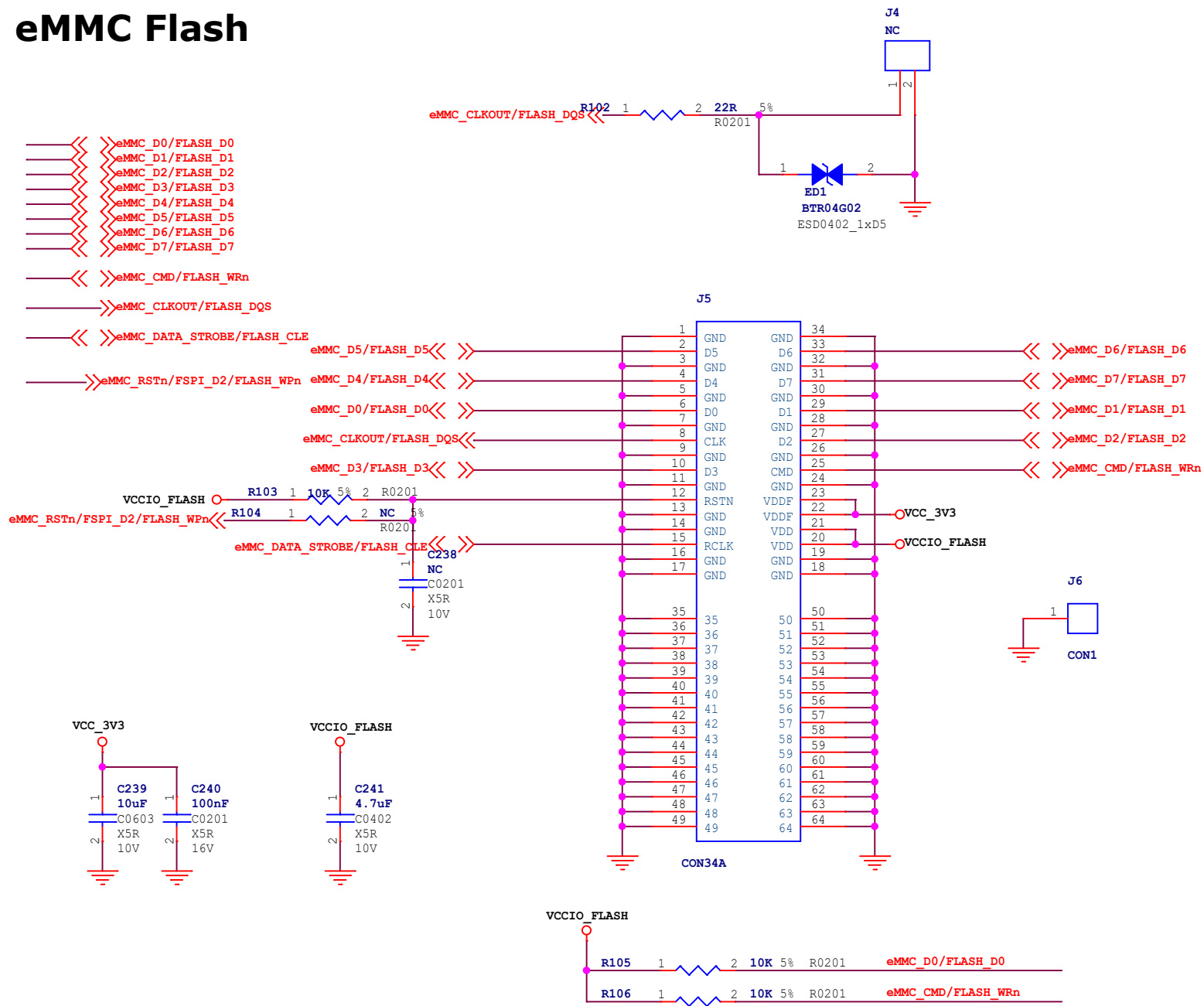
MIPI_DSI_TX 2Lanes



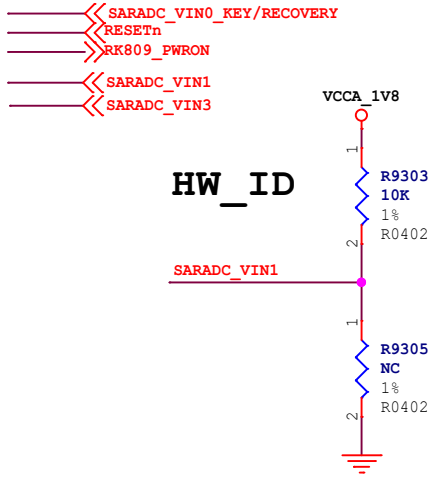
MIPI_CSI_RX 2Lanes



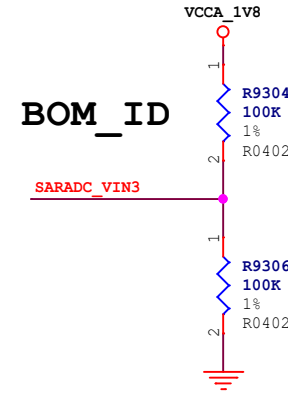
eMMC Flash



Size	Title: Gong Le	REV
A4	Page Name: eMMC Flash	V1.3
Date: Tuesday, October 26, 2021	Sheet 23 of 33	

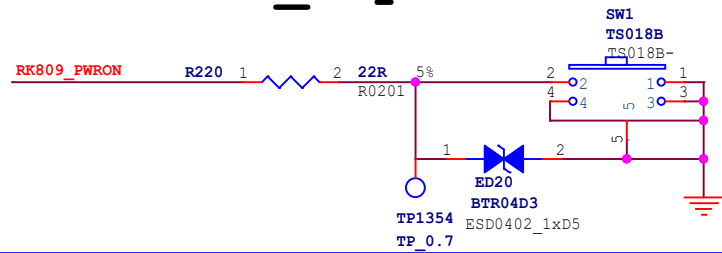


SARADC_VIN1	Up Resistance	Down Resistance
HW_ID0	10K	DNP
HW_ID1	10K	110K
HW_ID2	20K	100K
HW_ID3	33K	100K
HW_ID4	18K	36K
HW_ID5	36K	51K
HW_ID6	51K	51K
HW_ID7	51K	36K
HW_ID8	36K	18K
HW_ID9	100K	33K
HW_ID10	100K	20K
HW_ID11	110K	10K
HW_ID12	DNP	10K

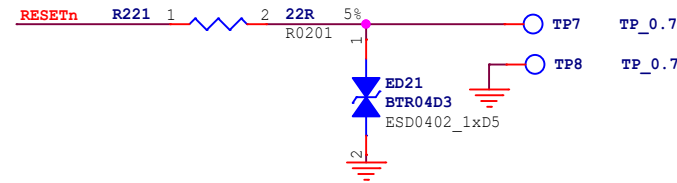


SARADC_VIN3	Up Resistance	Down Resistance
G	10K	DNP
A	DNP	100K
B	100K	20K
C	100K	51K
D	100K	100K
E		
F		
NC	DNP	DNP
I	20K	100K
J	18K	36K

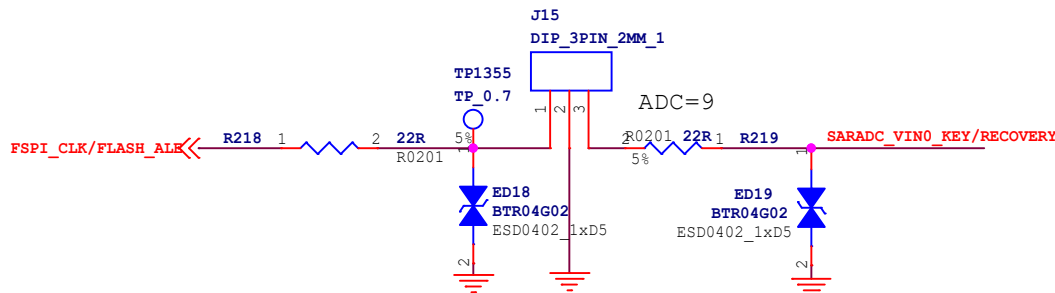
PowerOn/OFF_Key



Reset_Key



RECOVERY



Note:

If there is no Key requirement, It is suggested to reserve a SW9200 Key to facilitate the development debug

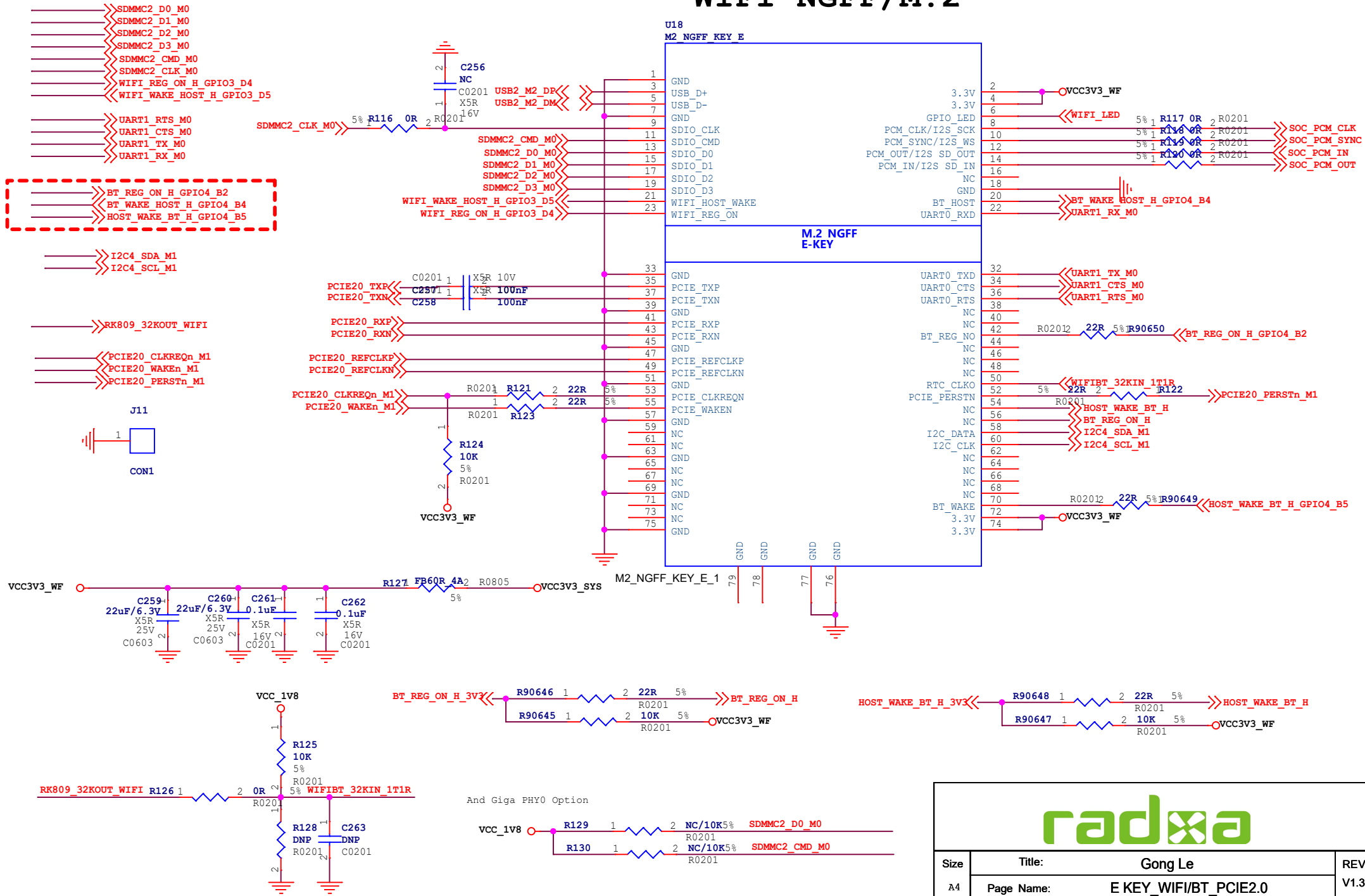
RECOVERY Key function:
If SARADC_VIN0=0V at after power on and reset, then system will enter into loader mode.




Size	Title: Gong Le	REV
A4	Page Name: SARADC_KEY	V1.3
Date: Wednesday, April 27, 2022		Sheet 24 of 33

SDIO WIFI/BT MODULE

WIFI NGFF/M.2

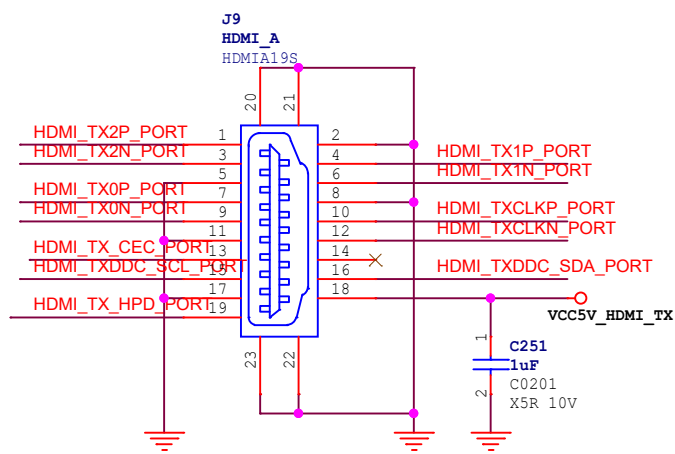
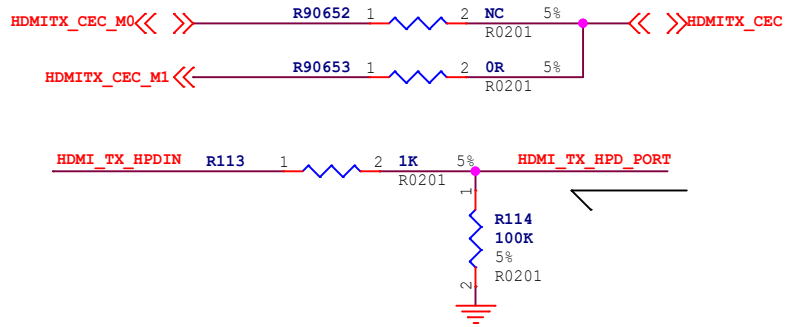
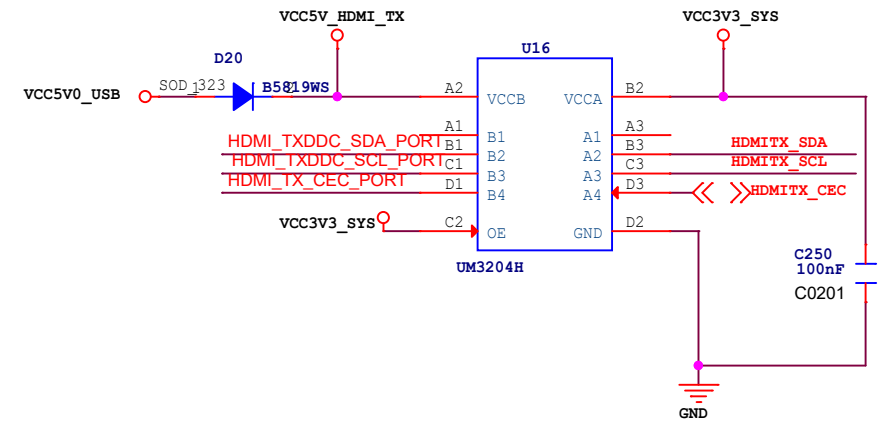
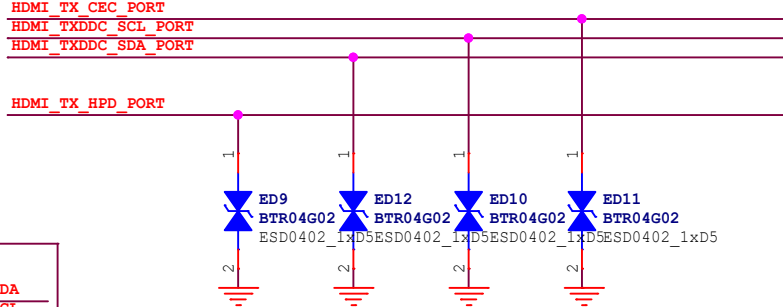
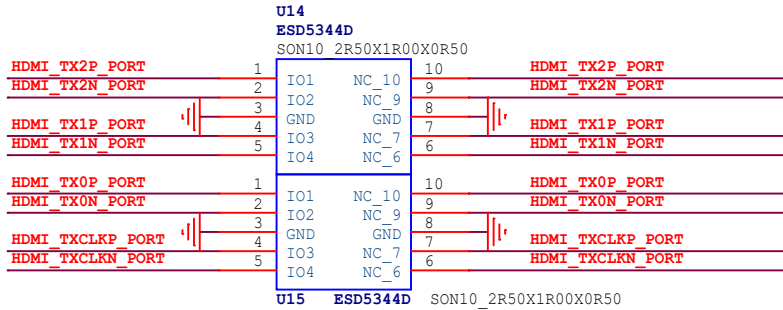
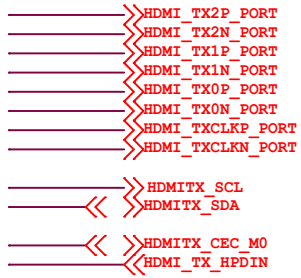




Size	Title: Gong Le	REV
A4	Page Name: E KEY_WIFI/BT_PCIE2.0	V1.3
Date: Tuesday, October 26, 2021	Sheet	25 of 33

HDMI2.0 TX

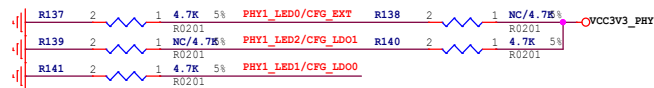
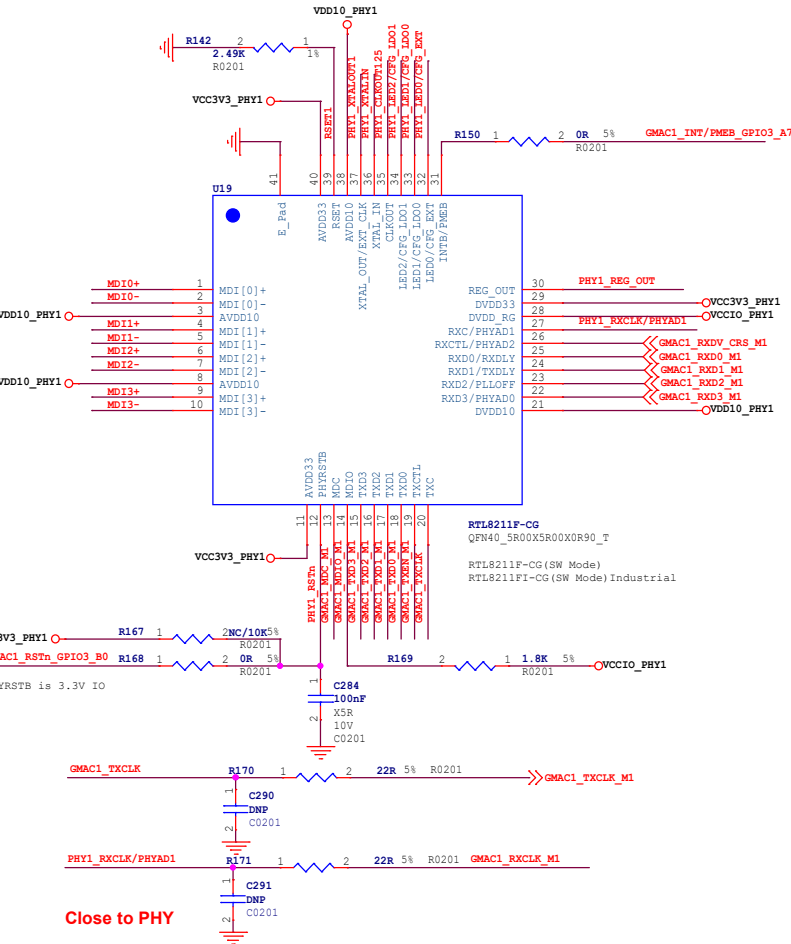
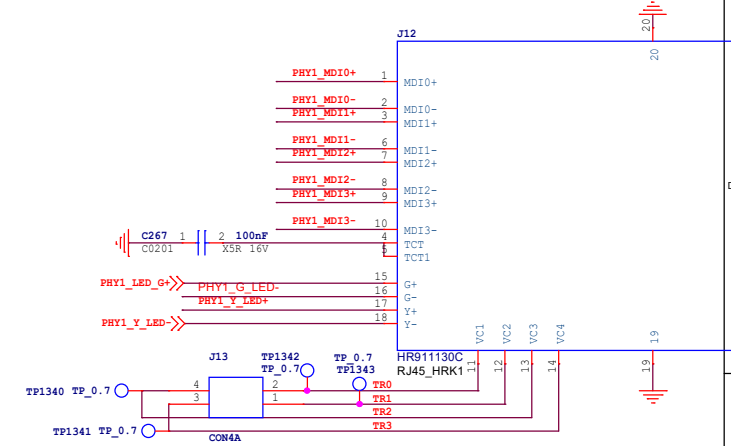
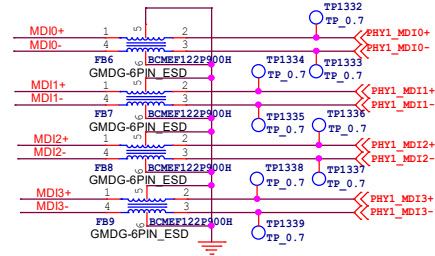
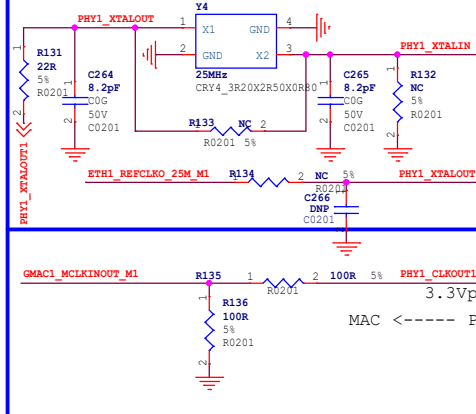
$C_j \leq 0.4 \text{ pF}$



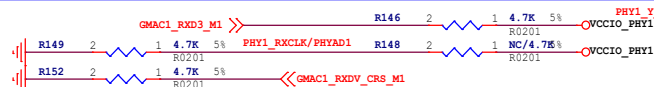
radxa		
Size	Title:	Gong Le
A4	Page Name:	HDMI
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		REV V1.3

Giga PHY1

- >>> GMAC1_TXD0_M1
- >>> GMAC1_TXD1_M1
- >>> GMAC1_TXD2_M1
- >>> GMAC1_TXD3_M1
- >>> GMAC1_TXEN_M1
- >>> GMAC1_TXCLK_M1
- >>> GMAC1_RXD0_M1
- >>> GMAC1_RXD1_M1
- >>> GMAC1_RXD2_M1
- >>> GMAC1_RXD3_M1
- >>> GMAC1_RXDV_CRS_M1
- >>> GMAC1_RXCLK_M1
- >>> ETH1_REFCLK0_25M_M1
- >>> GMAC1_MCLKINOUT_M1
- >>> GMAC1_MDC_M1
- >>> GMAC1_MDIO_M1
- >>> GMAC1_RSTn_GPIO3_B0
- >>> GMAC1_INT/PMEB_GPIO3_A7

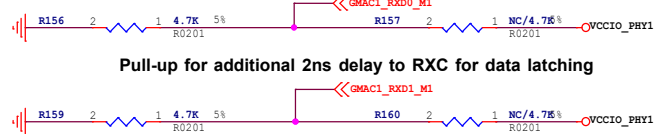


VCC_PHY0_IO Voltage Config

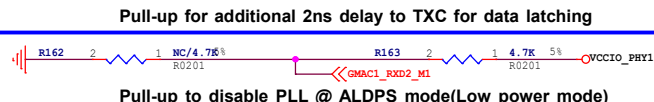


PHY Address Config

PHY Address PHYAD[2:0]
1 (default) 3'b001



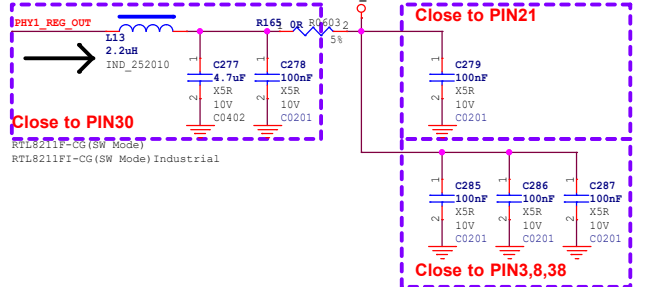
Pull-up for additional 2ns delay to RXC for data latching



Pull-up for additional 2ns delay to TXC for data latching



Pull-up to disable PLL @ ALDPS mode (Low power mode)

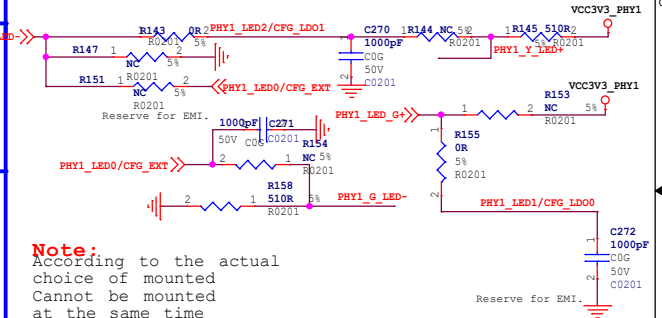


Close to PIN30

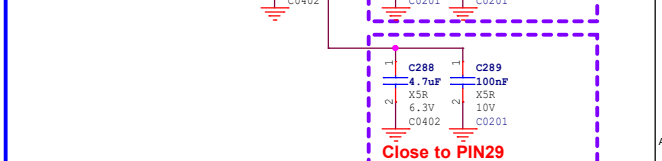
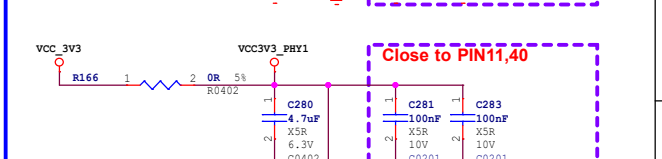
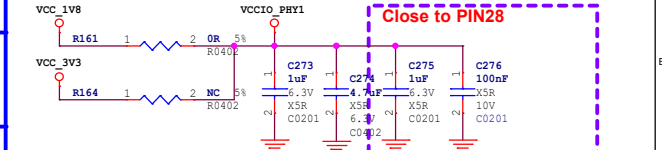
Close to PIN21

Close to PIN3,8,38

RGMI Power Source	CFG EXT	CFG LDO[1:0]	
External 3.3V	1'b1	2'b00	
External 1.8V	1'b1	2'b10	
Internal 1.8V(default)	1'b0	2'b10	



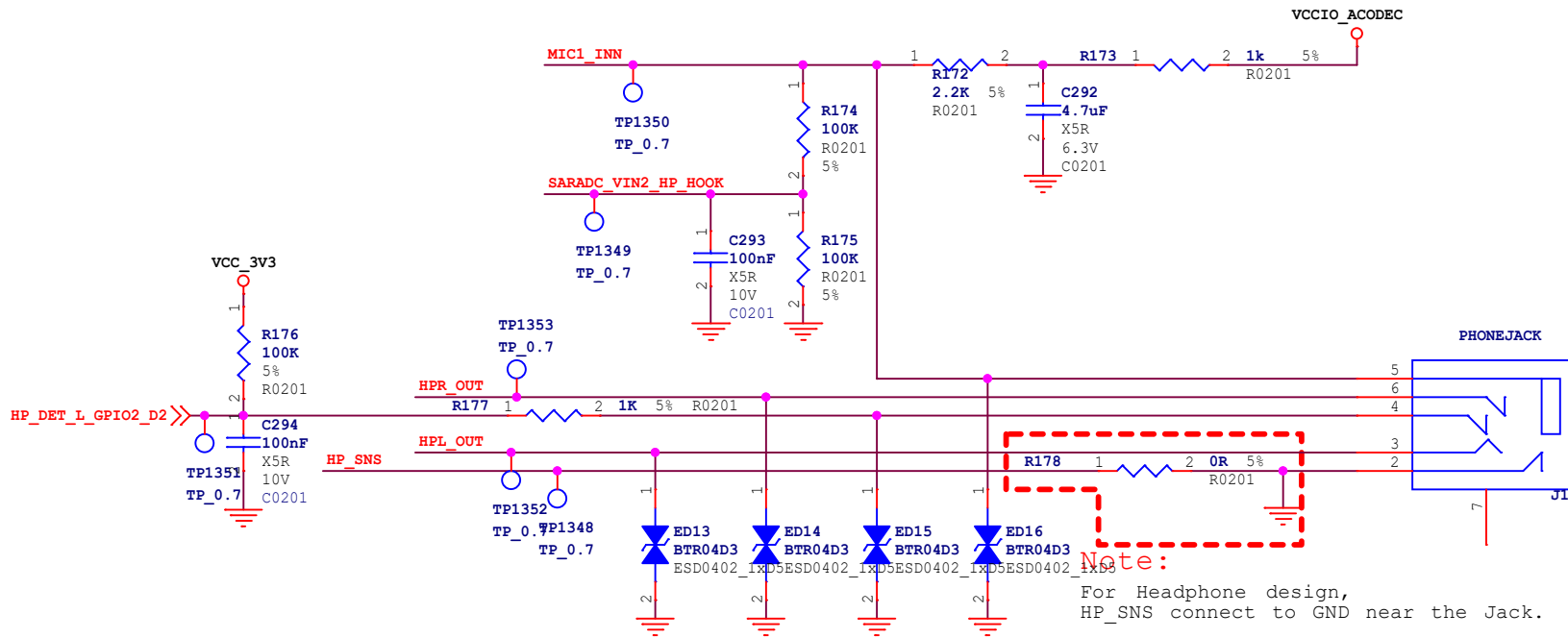
Note: According to the actual choice of mounted cannot be mounted at the same time



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- HPL_OUT
- HP_SNS
- HPR_OUT
- ← HP_DET_L_GPIO2_D2
- ← MIC1_INN
- ← SARADC_VIN2_HP_HOOK

Headphone Jack(4-pole with DET & MIC) Option



Note:
For Headphone design,
HP_SNS connect to GND near the Jack.

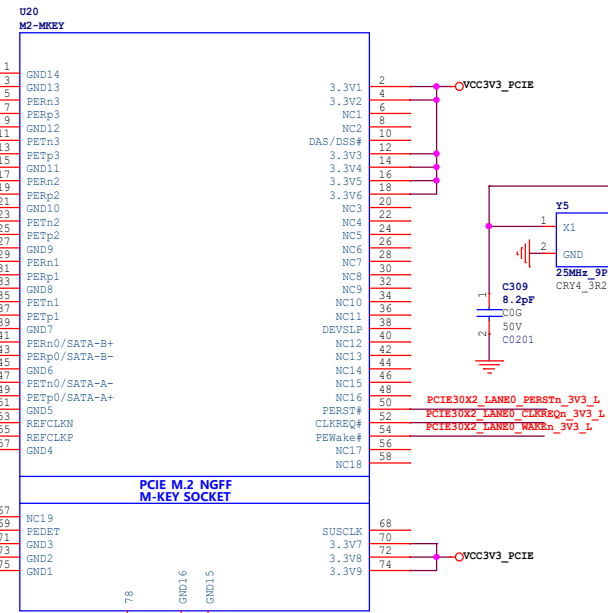
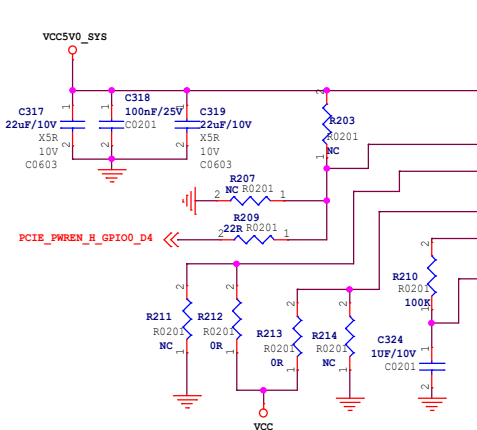
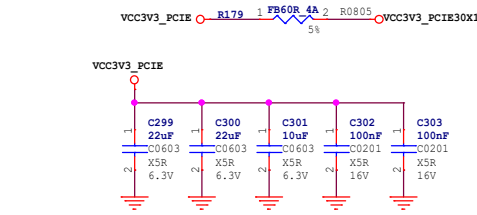


Size	Title: Gong Le	REV
A4	Page Name: Headphone	V1.3
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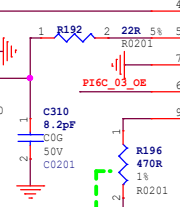
PCIE30X2_CLKREQn_M1 R180 1 22R 5% 2 PCIE30X2_LANE0_CLKREQn_3V3_L R0201
 PCIE30X2_WAKEn_M1 R181 1 22R 5% 2 PCIE30X2_LANE0_WAKEn_3V3_L R0201
 PCIE30X2_PERStn_M1 R182 1 22R 5% 2 PCIE30X2_LANE0_PERStn_3V3_L R0201

>>>PCIE30_TXOP
 >>>PCIE30_TXON
 >>>PCIE30_TXIP
 >>>PCIE30_TXIN
 >>>PCIE30_RXOP
 >>>PCIE30_RXON
 >>>PCIE30_RXIP
 >>>PCIE30_RXIN
 >>>PCIE30_REFCLKP_IN
 >>>PCIE30_REFCLKN_IN
 >>>PCIE30X2_CLKREQn_M1
 >>>PCIE30X2_WAKEn_M1
 >>>PCIE30X2_PERStn_M1
 >>>PCIE_PWREN_H_GPI00_D4

PCIE30_RXIN
 PCIE30_RXIP
 PCIE30_TXIN
 PCIE30_TXIP
 PCIE30_RXON
 PCIE30_RXOP
 PCIE30_TXON
 PCIE30_TXOP
 PCIE30_REFCLKN_CON
 PCIE30_REFCLKP_CON



PI6C_03_S0 1 S0 VDDX
 PI6C_03_S1 2 S1 VDDA
 PI6C_03_SS0 3 SS0
 PI6C_03_SS1 4 SS1

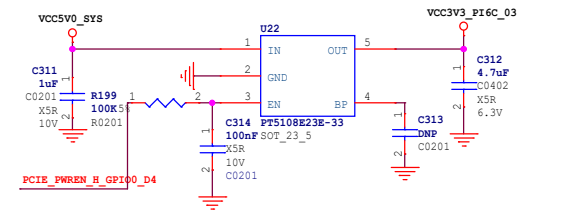
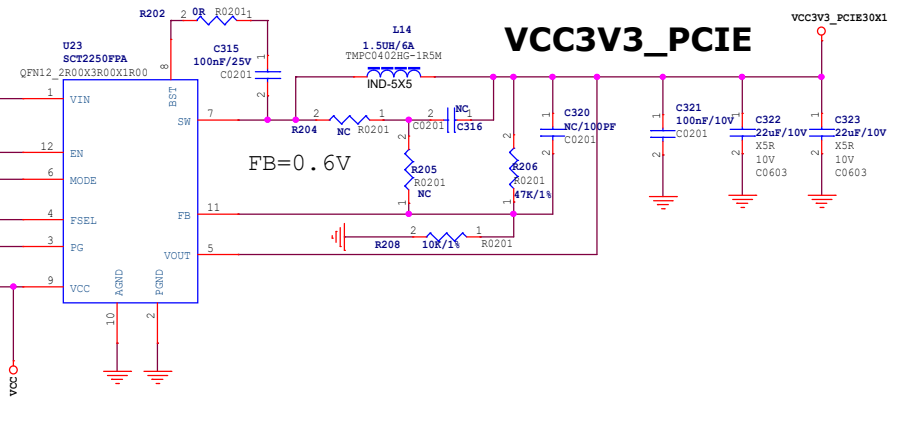


If board target trace impedance is 50ohm then R = 475ohm providing an IREF of 2.32 mA . The output current (IOH) is 6 * IREF . 6x2.32X50=696mV

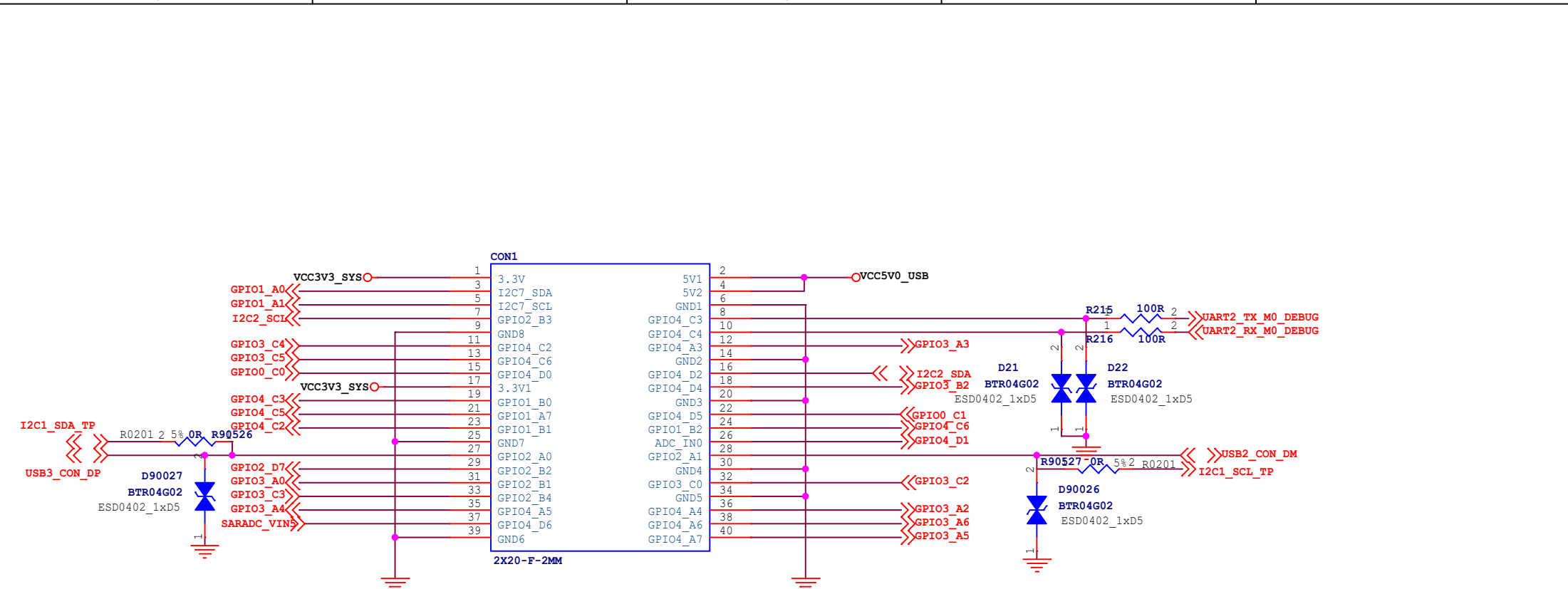
PI6C_S1	PI6C_S0	Out Freq
0	1	100MHz

PI6C_SS1	PI6C_SS0	Spread %
0	0	No Spread
0	1	-0.5
1	0	-1.0
1	1	No Spread

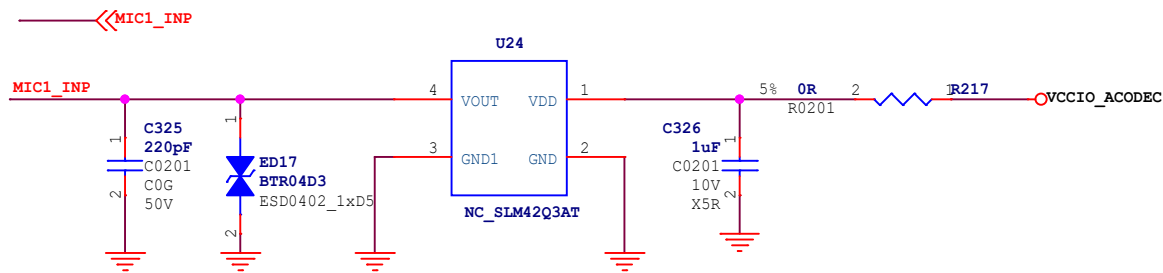
VCC3V3_PCIE



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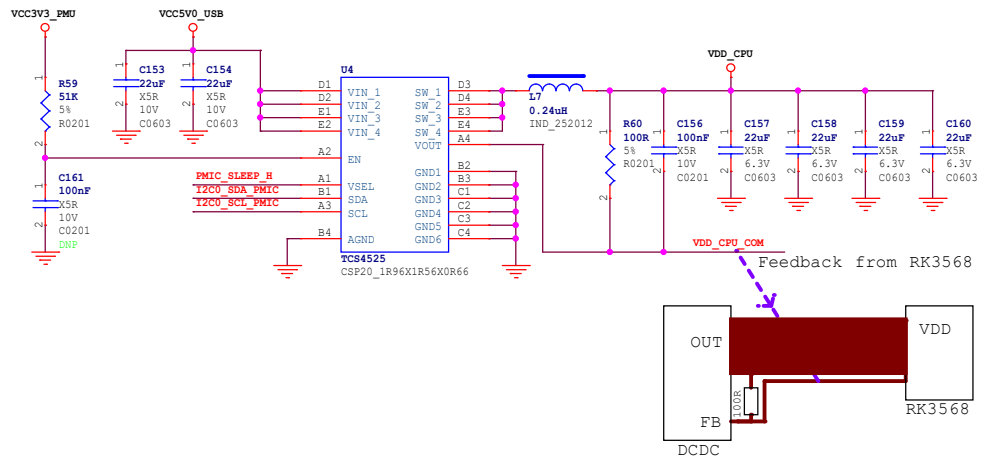
MIC



Size	Title:	Gong Le	REV
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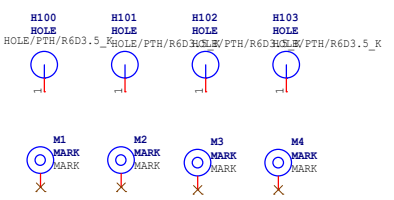
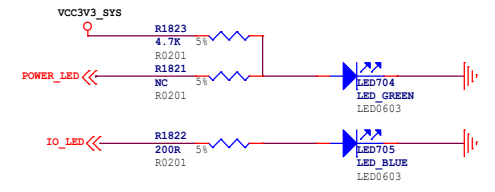
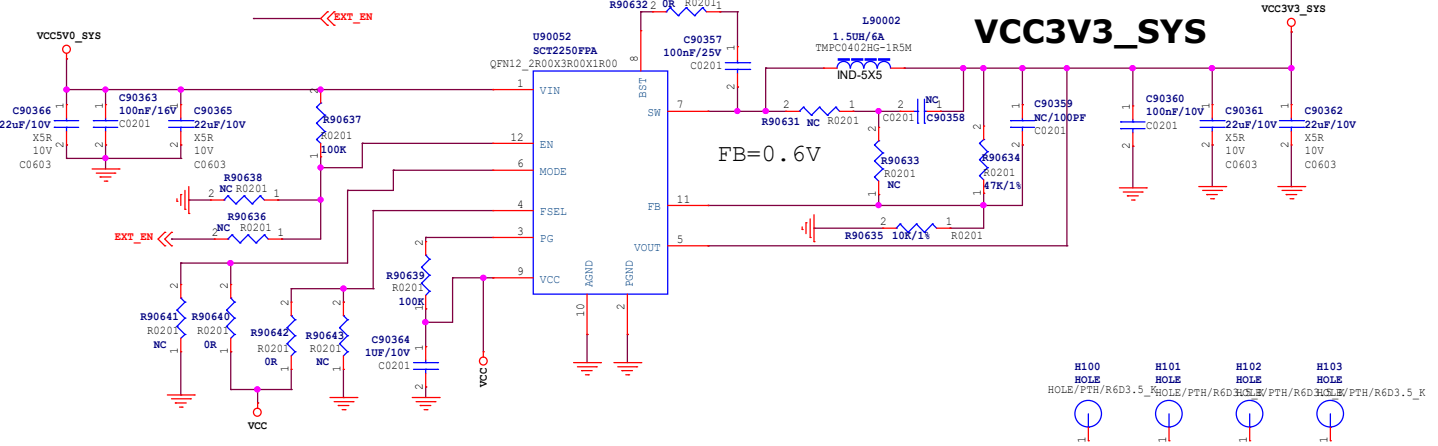
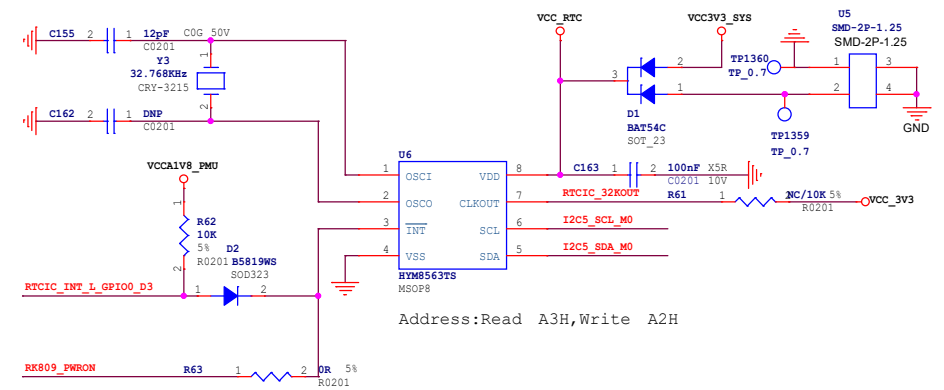
I2C0_SCL_PMIC
 I2C0_SDA_PMIC
 PMIC_SLEEP_H
 VDD_CPU_COM
 RTCIC_INT_L_GPIO0_D3
 RTCIC_32KOUT
 I2C5_SCL_M0
 I2C5_SDA_M0
 RK809_PWRON

VDD_CPU



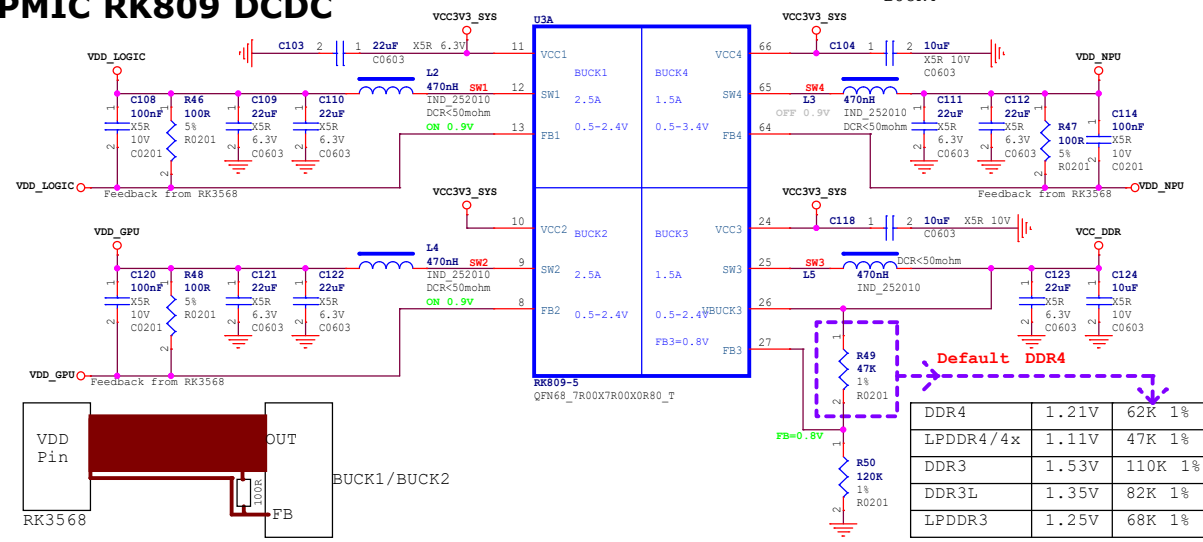
RTC IC --Option

Note:
 The power off hold time scheme is required,
 It is recommended to use external RTC IC
 But, it will not support the timing poweron function

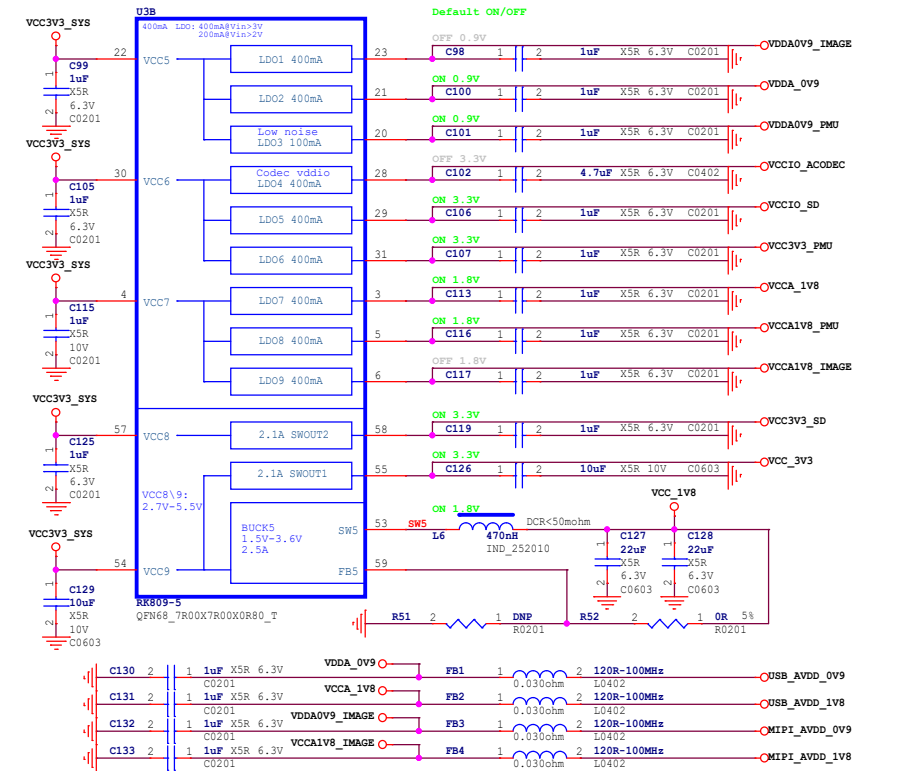




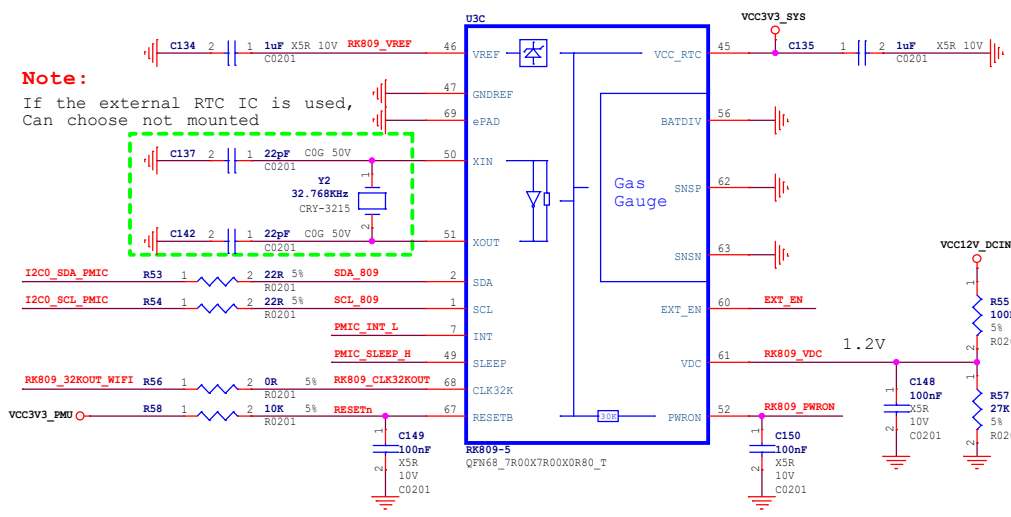
PMIC RK809 DCDC



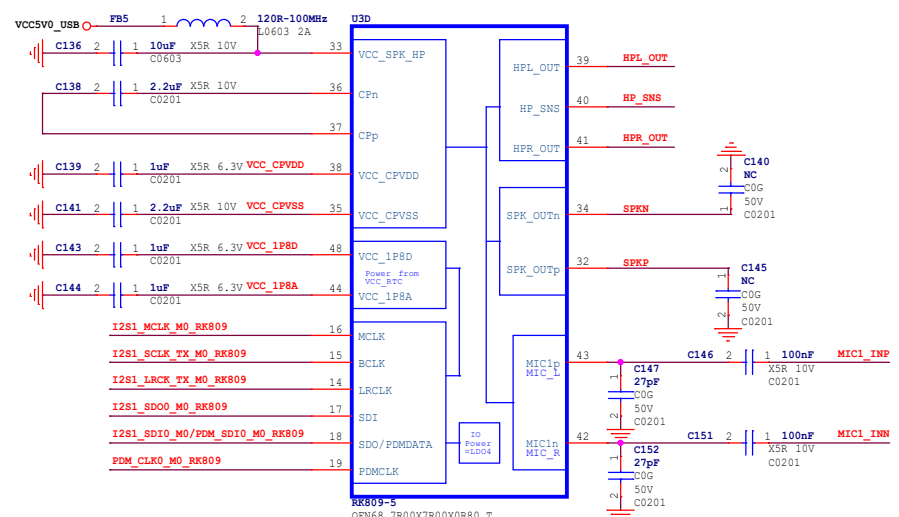
PMIC RK809 LDO



PMIC RK809 Management



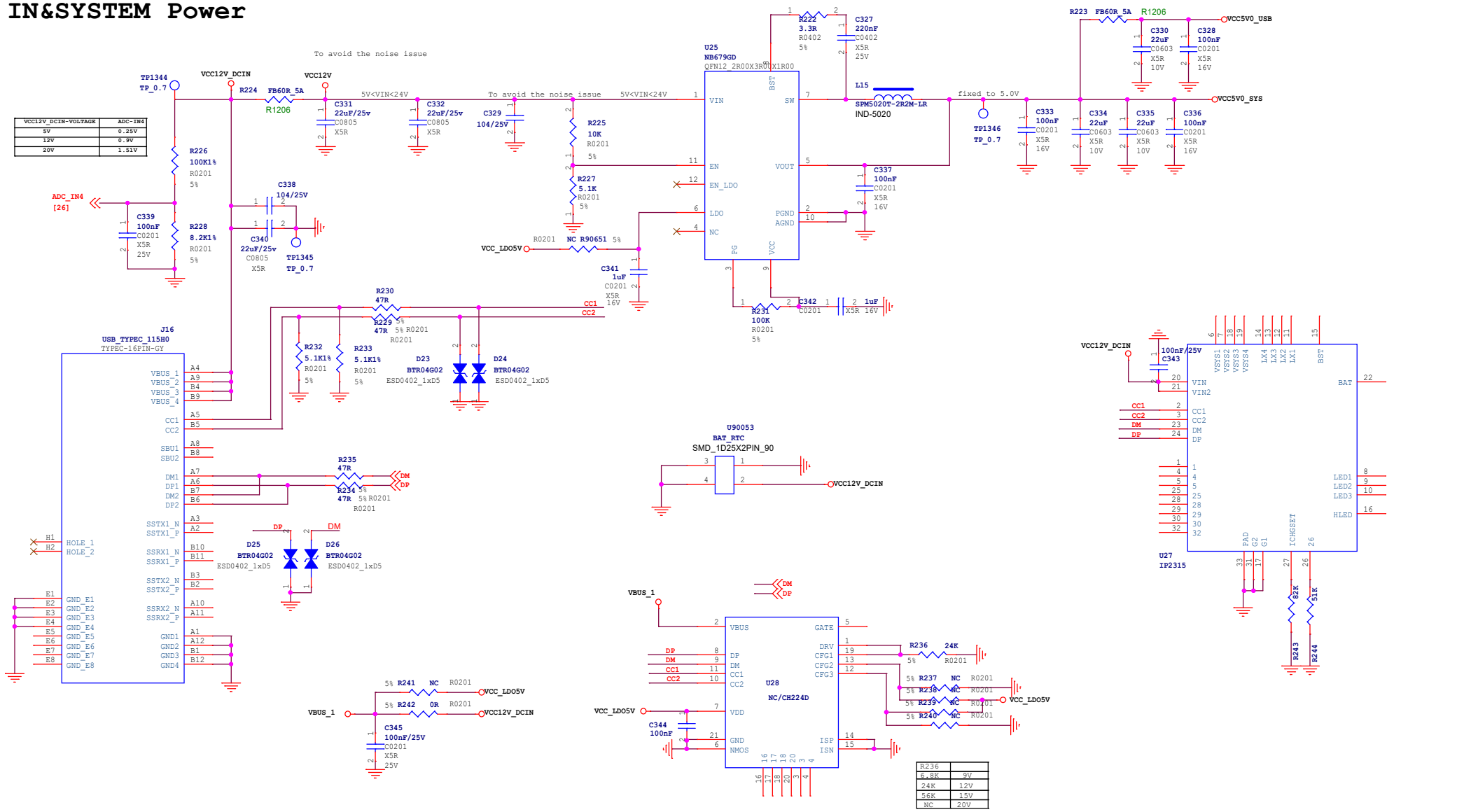
PMIC RK809 CODEC



Note:
If RK809-5 codec is not used, then Pin 14,15,16,17,19,40 Tie VSS Pin 18,36,37,38,39,41,34,32,43,42 Leave floating




DC IN&SYSTEM Power



VCC12V DCIN-VOLTAGE	ADC_IN4
5V	0.25V
12V	0.9V
20V	1.51V

R236	5.8K	9V
	24K	12V
	56K	15V
	NC	20V



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